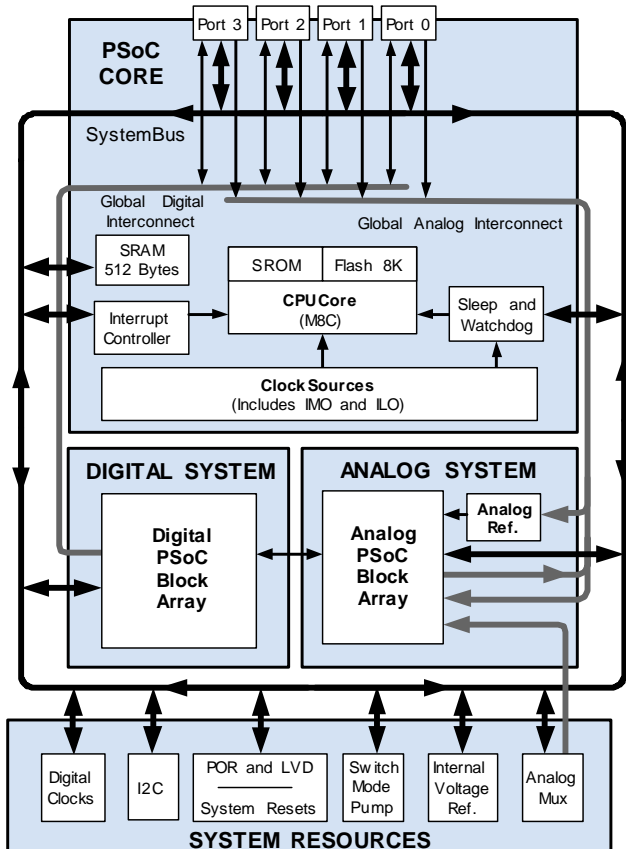


CY8C21234, CY8C21334, CY8C21434, CY8C21534, and CY8C21634



Features

- **Powerful Harvard Architecture Processor**
 - M8C Processor Speeds to 24 MHz
 - Low Power at High Speed
 - 2.4V to 5.25V Operating Voltage
 - Operating Voltages Down to 1.0V Using On-Chip Switch Mode Pump (SMP)
 - Industrial Temperature Range: -40°C to +85°C
- **Advanced Peripherals (PSoC Blocks)**
 - 4 Analog Type "E" PSoC Blocks Provide:
 - 2 Comparators with DAC Refs
 - Two 8-Bit 28 Channel ADCs
 - 4 Digital PSoC Blocks Provide:
 - 8- to 32-Bit Timers, Counters, and PWMs
 - CRC and PRS Modules
 - Full-Duplex UART, SPI™ Master or Slave
 - Connectable to All GPIO Pins
 - Complex Peripherals by Combining Blocks
- **Flexible On-Chip Memory**
 - 8K Flash Program Storage 50,000 Erase/Write Cycles
 - 512 Bytes SRAM Data Storage
 - In-System Serial Programming (ISSP™)
 - Partial Flash Updates
 - Flexible Protection Modes
 - EEPROM Emulation in Flash
- **Complete Development Tools**
 - Free Development Software (PSoC™ Designer)
 - Full-Featured, In-Circuit Emulator and Programmer
 - Full Speed Emulation
 - Complex Breakpoint Structure
 - 128K Bytes Trace Memory
- **Precision, Programmable Clocking**
 - Internal ±2.5% 24/48 MHz Oscillator
 - Internal Oscillator for Watchdog and Sleep
- **Programmable Pin Configurations**
 - 25 mA Drive on All GPIO
 - Pull Up, Pull Down, High Z, Strong, or Open Drain Drive Modes on All GPIO
 - Up to 8 Analog Inputs on GPIO
 - Configurable Interrupt on All GPIO
- **Versatile Analog Mux**
 - Common Internal Analog Bus
 - Simultaneous Connection of IO Combinations
 - Capacitive Sensing Application Capability
- **Additional System Resources**
 - I²C™ Master, Slave and Multi-Master to 400 kHz
 - Watchdog and Sleep Timers
 - User-Configurable Low Voltage Detection
 - Integrated Supervisory Circuit
 - On-Chip Precision Voltage Reference



PSoC™ Functional Overview

The PSoC™ family consists of many *Mixed-Signal Array with On-Chip Controller* devices. These devices are designed to replace multiple traditional MCU-based system components with one, low cost single-chip programmable component. A PSoC device includes configurable blocks of analog and digital logic, as well as programmable interconnect. This architecture allows the user to create customized peripheral configurations, to match the requirements of each individual application. Additionally, a fast CPU, Flash program memory, SRAM data memory, and configurable IO are included in a range of convenient pinouts.

The PSoC architecture, as illustrated on the left, is comprised of four main areas: the Core, the System Resources, the Digital System, and the Analog System. Configurable global bus resources allow all the device resources to be combined into a complete custom system. Each CY8C21x34 PSoC device includes four digital blocks and four analog blocks. Depending on the PSoC package, up to 28 general purpose IO (GPIO) are also included. The GPIO provide access to the global digital and analog interconnects.

The PSoC Core

The PSoC Core is a powerful engine that supports a rich instruction set. It encompasses SRAM for data storage, an interrupt controller, sleep and watchdog timers, and IMO (internal main oscillator) and ILO (internal low speed oscillator). The

CPU core, called the M8C, is a powerful processor with speeds up to 24 MHz. The M8C is a four MIPS 8-bit Harvard architecture microprocessor.

System Resources provide additional capability, such as digital clocks to increase the flexibility of the PSoC mixed-signal arrays, I2C functionality for implementing an I2C master, slave, MultiMaster, an internal voltage reference that provides an absolute value of 1.3V to a number of PSoC subsystems, a switch mode pump (SMP) that generates normal operating voltages off a single battery cell, and various system resets supported by the M8C.

The Digital System is composed of an array of digital PSoC blocks, which can be configured into any number of digital peripherals. The digital blocks can be connected to the GPIO through a series of global buses that can route any signal to any pin. Freeing designs from the constraints of a fixed peripheral controller.

The Analog System is composed of four analog PSoC blocks, supporting comparators and analog-to-digital conversion up to 8 bits in precision.

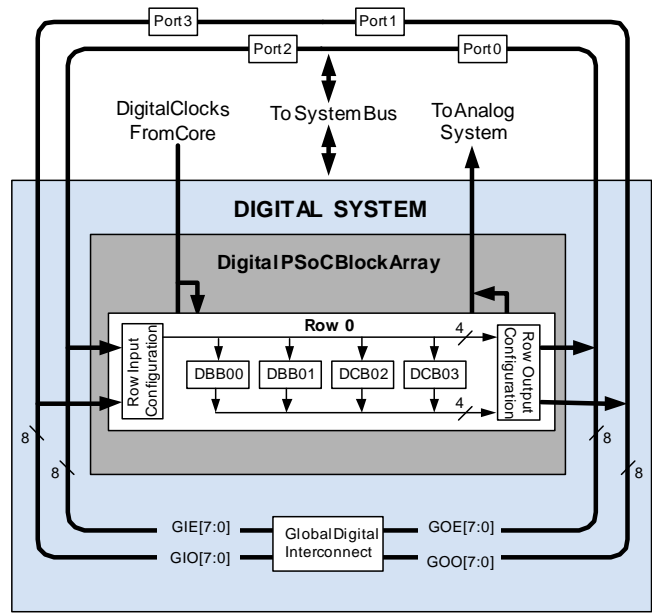
The Digital System

The Digital System is composed of 4 digital PSoC blocks. Each block is an 8-bit resource that can be used alone or combined with other blocks to form 8, 16, 24, and 32-bit peripherals, which are called user module references. Digital peripheral configurations include those listed below.

- PWMs (8 to 32 bit)
- PWMs with Dead band (8 to 32 bit)
- Counters (8 to 32 bit)
- Timers (8 to 32 bit)
- UART 8 bit with selectable parity
- SPI master and slave
- I2C slave and multi-master
- Cyclical Redundancy Checker/Generator (8 to 32 bit)
- IrDA
- Pseudo Random Sequence Generators (8 to 32 bit)

The digital blocks can be connected to any GPIO through a series of global buses that can route any signal to any pin. The buses also allow for signal multiplexing and for performing logic operations. This configurability frees your designs from the constraints of a fixed peripheral controller.

Digital blocks are provided in rows of four, where the number of blocks varies by PSoC device family. This allows you the optimum choice of system resources for your application. Family resources are shown in the table titled “PSoC Device Characteristics” on page 3.



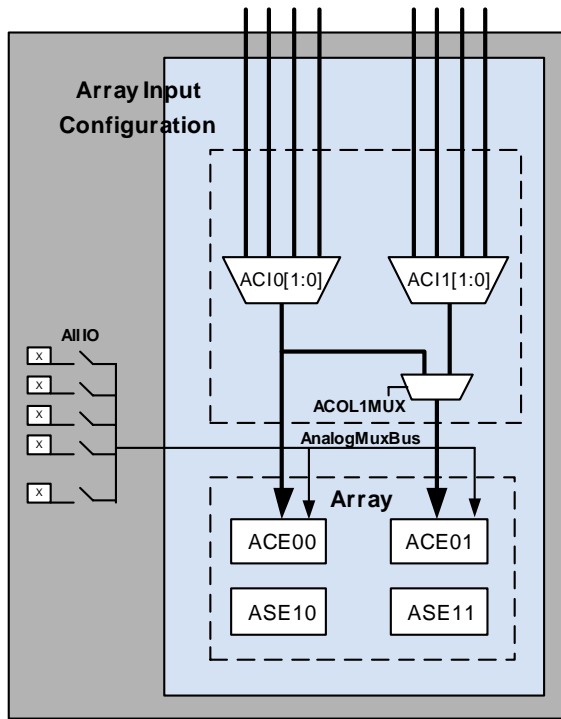
Digital System Block Diagram

The Analog System

The Analog System is composed of 4 configurable blocks, allowing the creation of complex analog signal flows. Analog peripherals are very flexible and can be customized to support specific application requirements. Some of the common PSoC analog functions for this device (most available as user modules) are listed below.

- Analog-to-digital converters (up to 2, with 8-bit resolution)
- Pin-to-pin comparator
- Single-ended comparators (up to 2) with absolute (1.3V) reference or 8-bit DAC reference
- 1.3V reference (as a System Resource)

In most PSoC devices, analog blocks are provided in columns of three, which includes one CT (Continuous Time) and two SC (Switched Capacitor) blocks. The CY8C21x34 devices provide limited functionality Type “E” analog blocks. Each column contains one CT Type E block and one SC Type E block. Refer to the *PSoC Mixed-Signal Array Technical Reference Manual* for detailed information on the CY8C21x34’s Type E analog blocks.



Analog System Block Diagram

The Analog Multiplexer System

The Analog Mux Bus can connect to every GPIO pin. Pins can be connected to the bus individually or in any combination. The bus also connects to the analog system for analysis with comparators and analog-to-digital converters. An additional 8:1 analog input multiplexer provides a second path to bring Port 0 pins to the analog array.

Switch control logic enables selected pins to precharge continuously under hardware control. This enables capacitive measurement for applications such as touch sensing. Other multiplexer applications include:

- Track pad, finger sensing.
- Chip-wide mux that allows analog input from any IO pin.
- Crosspoint connection between any IO pin combinations.

Additional System Resources

System Resources, some of which have been previously listed, provide additional capability useful to complete systems. Additional resources include a switch mode pump, low voltage detection, and power on reset. Brief statements describing the merits of each system resource are presented below.

- Digital clock dividers provide three customizable clock frequencies for use in applications. The clocks can be routed to both the digital and analog systems. Additional clocks can be generated using digital PSoC blocks as clock dividers.
- The I2C module provides 100 and 400 kHz communication over two wires. Slave, master, and multi-master modes are all supported.
- Low Voltage Detection (LVD) interrupts can signal the application of falling voltage levels, while the advanced POR (Power On Reset) circuit eliminates the need for a system supervisor.
- An internal 1.3 voltage reference provides an absolute reference for the analog system, including ADCs and DACs.
- An integrated switch mode pump (SMP) generates normal operating voltages from a single 1.2V battery cell, providing a low cost boost converter.
- Versatile analog multiplexer system.

PSoC Device Characteristics

Depending on your PSoC device characteristics, the digital and analog systems can have 16, 8, or 4 digital blocks and 12, 6, or 4 analog blocks. The following table lists the resources available for specific PSoC device groups. The PSoC device covered by this data sheet is highlighted below.

PSoC Device Characteristics

| PSoC Part Number | Digital IO | Digital Rows | Digital Blocks | Analog Inputs | Analog Outputs | Analog Columns | Analog Blocks | SRAM Size | Flash Size |
|------------------|-----------------|--------------|----------------|---------------|----------------|----------------|----------------------|------------------|------------|
| CY8C29x66 | up to 64 | 4 | 16 | 12 | 4 | 4 | 12 | 2K | 32K |
| CY8C24794 | up to 56 | 1 | 4 | 48 | 2 | 2 | 6 | 1K | 16K |
| CY8C27x43 | up to 44 | 2 | 8 | 12 | 4 | 4 | 12 | 256 Bytes | 16K |
| CY8C24x23 | up to 24 | 1 | 4 | 12 | 2 | 2 | 6 | 256 Bytes | 4K |
| CY8C24x23A | up to 24 | 1 | 4 | 12 | 2 | 2 | 6 | 256 Bytes | 4K |
| CY8C21x34 | up to 28 | 1 | 4 | 28 | 0 | 2 | 4^a | 512 Bytes | 8K |
| CY8C21x23 | 16 | 1 | 4 | 8 | 0 | 2 | 4 ^a | 256 Bytes | 4K |

a. Limited analog functionality.

Getting Started

The quickest path to understanding the PSoC silicon is by reading this data sheet and using the PSoC Designer Integrated Development Environment (IDE). This data sheet is an overview of the PSoC integrated circuit and presents specific pin, register, and electrical specifications. For in-depth information, along with detailed programming information, reference the *PSoC Mixed-Signal Array Technical Reference Manual*, which can be found on <http://www.cypress.com/psoc>.

For up-to-date Ordering, Packaging, and Electrical Specification information, reference the latest PSoC device data sheets on the web at <http://www.cypress.com>.

Development Kits

Development Kits are available from the following distributors: Digi-Key, Avnet, Arrow, and Future. The Cypress Online Store contains development kits, C compilers, and all accessories for PSoC development. Go to the Cypress Online Store web site at <http://www.cypress.com>, click the Online Store shopping cart icon at the bottom of the web page, and click *PSoC (Programmable System-on-Chip)* to view a current list of available items.

Technical Training

Free PSoC technical training is available for beginners and is taught by a marketing or application engineer over the phone. PSoC training classes cover designing, debugging, advanced analog, as well as application-specific classes covering topics such as PSoC and the LIN bus. Go to <http://www.cypress.com>, click on Design Support located on the left side of the web page, and select Technical Training for more details.

Consultants

Certified PSoC Consultants offer everything from technical assistance to completed PSoC designs. To contact or become a PSoC Consultant go to <http://www.cypress.com>, click on Design Support located on the left side of the web page, and select CYPros Consultants.

Technical Support

PSoC application engineers take pride in fast and accurate response. They can be reached with a 4-hour guaranteed response at <http://www.cypress.com/support/login.cfm>.

Application Notes

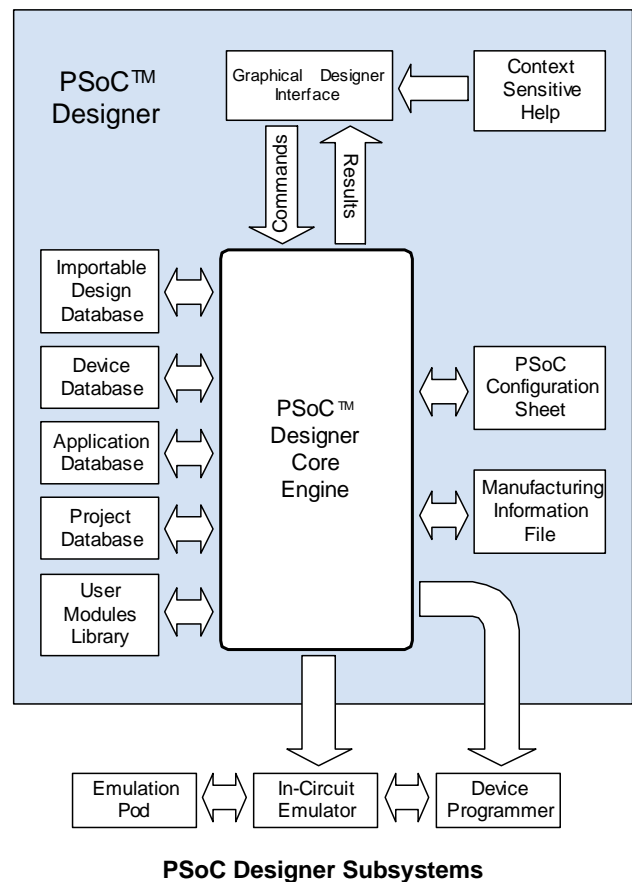
A long list of application notes will assist you in every aspect of your design effort. To view the PSoC application notes, go to the <http://www.cypress.com> web site and select Application Notes under the Design Resources list located in the center of the web page. Application notes are organized by part number.

Development Tools

The Cypress MicroSystems PSoC Designer is a Microsoft® Windows-based, integrated development environment for the Programmable System-on-Chip (PSoC) devices. The PSoC Designer IDE and application runs on Windows NT 4.0, Windows 2000, Windows Millennium (Me), or Windows XP. (Reference the PSoC Designer Functional Flow diagram below.)

PSoC Designer helps the customer to select an operating configuration for the PSoC, write application code that uses the PSoC, and debug the application. This system provides design database management by project, an integrated debugger with In-Circuit Emulator, in-system programming support, and the CYASM macro assembler for the CPUs.

PSoC Designer also supports a high-level C language compiler developed specifically for the devices in the family.



PSoC Designer Software Subsystems

Device Editor

The device editor subsystem allows the user to select different onboard analog and digital components called user modules using the PSoC blocks. Examples of user modules are ADCs, DACs, Amplifiers, and Filters.

The device editor also supports easy development of multiple configurations and dynamic reconfiguration. Dynamic reconfiguration allows for changing configurations at run time.

PSoC Designer sets up power-on initialization tables for selected PSoC block configurations and creates source code for an application framework. The framework contains software to operate the selected components and, if the project uses more than one operating configuration, contains routines to switch between different sets of PSoC block configurations at run time. PSoC Designer can print out a configuration sheet for a given project configuration for use during application programming in conjunction with the Device Data Sheet. Once the framework is generated, the user can add application-specific code to flesh out the framework. It's also possible to change the selected components and regenerate the framework.

Design Browser

The Design Browser allows users to select and import preconfigured designs into the user's project. Users can easily browse a catalog of preconfigured designs to facilitate time-to-design. Examples provided in the tools include a 300-baud modem, LIN Bus master and slave, fan controller, and magnetic card reader.

Application Editor

In the Application Editor you can edit your C language and Assembly language source code. You can also assemble, compile, link, and build.

Assembler. The macro assembler allows the assembly code to be merged seamlessly with C code. The link libraries automatically use absolute addressing or can be compiled in relative mode, and linked with other software modules to get absolute addressing.

C Language Compiler. A C language compiler is available that supports Cypress MicroSystems' PSoC family devices. Even if you have never worked in the C language before, the product quickly allows you to create complete C programs for the PSoC family devices.

The embedded, optimizing C compiler provides all the features of C tailored to the PSoC architecture. It comes complete with embedded libraries providing port and bus operations, standard keypad and display support, and extended math functionality.

Debugger

The PSoC Designer Debugger subsystem provides hardware in-circuit emulation, allowing the designer to test the program in a physical system while providing an internal view of the PSoC device. Debugger commands allow the designer to read the program and read and write data memory, read and write IO registers, read and write CPU registers, set and clear breakpoints, and provide program run, halt, and step control. The debugger also allows the designer to create a trace buffer of registers and memory locations of interest.

Online Help System

The online help system displays online, context-sensitive help for the user. Designed for procedural and quick reference, each functional subsystem has its own context-sensitive help. This system also provides tutorials and links to FAQs and an Online Support Forum to aid the designer in getting started.

Hardware Tools

In-Circuit Emulator

A low cost, high functionality ICE (In-Circuit Emulator) is available for development support. This hardware has the capability to program single devices.

The emulator consists of a base unit that connects to the PC by way of a USB port. The base unit is universal and will operate with all PSoC devices. Emulation pods for each device family are available separately. The emulation pod takes the place of the PSoC device in the target board and performs full speed (24 MHz) operation.

Designing with User Modules

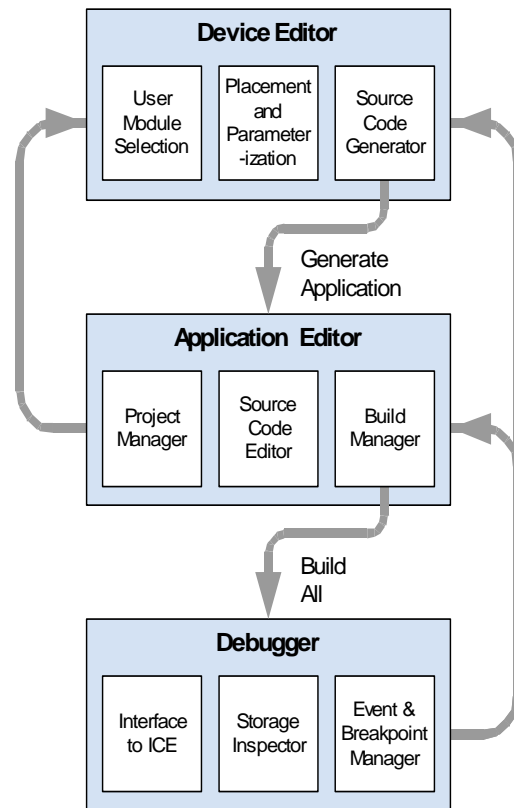
The development process for the PSoC device differs from that of a traditional fixed function microprocessor. The configurable analog and digital hardware blocks give the PSoC architecture a unique flexibility that pays dividends in managing specification change during development and by lowering inventory costs. These configurable resources, called PSoC Blocks, have the ability to implement a wide variety of user-selectable functions. Each block has several registers that determine its function and connectivity to other blocks, multiplexers, buses and to the IO pins. Iterative development cycles permit you to adapt the hardware as well as the software. This substantially lowers the risk of having to select a different part to meet the final design requirements.

To speed the development process, the PSoC Designer Integrated Development Environment (IDE) provides a library of pre-built, pre-tested hardware peripheral functions, called “User Modules.” User modules make selecting and implementing peripheral devices simple, and come in analog, digital, and mixed signal varieties. The standard User Module library contains over 50 common peripherals such as ADCs, DACs Timers, Counters, UARTs, and other not-so common peripherals such as DTMF Generators and Bi-Quad analog filter sections.

Each user module establishes the basic register settings that implement the selected function. It also provides parameters that allow you to tailor its precise configuration to your particular application. For example, a Pulse Width Modulator User Module configures one or more digital PSoC blocks, one for each 8 bits of resolution. The user module parameters permit you to establish the pulse width and duty cycle. User modules also provide tested software to cut your development time. The user module application programming interface (API) provides high-level functions to control and respond to hardware events at run time. The API also provides optional interrupt service routines that you can adapt as needed.

The API functions are documented in user module data sheets that are viewed directly in the PSoC Designer IDE. These data sheets explain the internal operation of the user module and provide performance specifications. Each data sheet describes the use of each user module parameter and documents the setting of each register controlled by the user module.

The development process starts when you open a new project and bring up the Device Editor, a graphical user interface (GUI) for configuring the hardware. You pick the user modules you need for your project and map them onto the PSoC blocks with point-and-click simplicity. Next, you build signal chains by interconnecting user modules to each other and the IO pins. At this stage, you also configure the clock source connections and enter parameter values directly or by selecting values from drop-down menus. When you are ready to test the hardware configuration or move on to developing code for the project, you perform the “Generate Application” step. This causes PSoC Designer to generate source code that automatically configures the device to your specification and provides the high-level user module API functions.



User Module and Source Code Development Flows

The next step is to write your main program, and any sub-routines using PSoC Designer's Application Editor subsystem. The Application Editor includes a Project Manager that allows you to open the project source code files (including all generated code files) from a hierarchical view. The source code editor provides syntax coloring and advanced edit features for both C and assembly language. File search capabilities include simple string searches and recursive “grep-style” patterns. A single mouse click invokes the Build Manager. It employs a professional-strength “makefile” system to automatically analyze all file dependencies and run the compiler and assembler as necessary. Project-level options control optimization strategies used by the compiler and linker. Syntax errors are displayed in a console window. Double clicking the error message takes you directly to the offending line of source code. When all is correct, the linker builds a HEX file image suitable for programming.

The last step in the development process takes place inside the PSoC Designer's Debugger subsystem. The Debugger downloads the HEX image to the In-Circuit Emulator (ICE) where it runs at full speed. Debugger capabilities rival those of systems costing many times more. In addition to traditional single-step, run-to-breakpoint and watch-variable features, the Debugger provides a large trace buffer and allows you define complex breakpoint events that include monitoring address and data bus values, memory locations and external signals.

Document Conventions

Acronyms Used

The following table lists the acronyms that are used in this document.

| Acronym | Description |
|---------|---|
| AC | alternating current |
| ADC | analog-to-digital converter |
| API | application programming interface |
| CPU | central processing unit |
| CT | continuous time |
| DAC | digital-to-analog converter |
| DC | direct current |
| ECO | external crystal oscillator |
| EEPROM | electrically erasable programmable read-only memory |
| FSR | full scale range |
| GPIO | general purpose IO |
| GUI | graphical user interface |
| HBM | human body model |
| ICE | in-circuit emulator |
| ILO | internal low speed oscillator |
| IMO | internal main oscillator |
| IO | input/output |
| IPOR | imprecise power on reset |
| LSb | least-significant bit |
| LVD | low voltage detect |
| MSb | most-significant bit |
| PC | program counter |
| PLL | phase-locked loop |
| POR | power on reset |
| PPOR | precision power on reset |
| PSoC™ | Programmable System-on-Chip™ |
| PWM | pulse width modulator |
| SC | switched capacitor |
| SLIMO | slow IMO |
| SMP | switch mode pump |
| SRAM | static random access memory |

Units of Measure

A units of measure table is located in the Electrical Specifications section. [Table 3-1 on page 15](#) lists all the abbreviations used to measure the PSoC devices.

Numeric Naming

Hexidecimal numbers are represented with all letters in uppercase with an appended lowercase 'h' (for example, '14h' or '3Ah'). Hexidecimal numbers may also be represented by a '0x' prefix, the C coding convention. Binary numbers have an appended lowercase 'b' (e.g., '01010100b' or '01000011b'). Numbers not indicated by an 'h', 'b', or 0x are decimal.

Table of Contents

For an in depth discussion and more information on your PSoC device, obtain the *PSoC Mixed-Signal Array Technical Reference Manual* on <http://www.cypress.com>. This document encompasses and is organized into the following chapters and sections.

| | |
|---|-----------|
| 1. Pin Information | 8 |
| 1.1 Pinouts | 8 |
| 1.1.1 16-Pin Part Pinout | 8 |
| 1.1.2 20-Pin Part Pinout | 9 |
| 1.1.3 28-Pin Part Pinout | 10 |
| 1.1.4 32-Pin Part Pinout | 11 |
| 2. Register Reference | 12 |
| 2.1 Register Conventions | 12 |
| 2.2 Register Mapping Tables | 12 |
| 3. Electrical Specifications | 15 |
| 3.1 Absolute Maximum Ratings | 16 |
| 3.2 Operating Temperature | 16 |
| 3.3 DC Electrical Characteristics | 16 |
| 3.3.1 DC Chip-Level Specifications | 16 |
| 3.3.2 DC General Purpose IO Specifications | 17 |
| 3.3.3 DC Operational Amplifier Specifications | 18 |
| 3.3.4 DC Switch Mode Pump Specifications | 19 |
| 3.3.5 DC Analog Mux Bus Specifications | 20 |
| 3.3.6 DC POR and LVD Specifications | 20 |
| 3.3.7 DC Programming Specifications | 21 |
| 3.4 AC Electrical Characteristics | 22 |
| 3.4.1 AC Chip-Level Specifications | 22 |
| 3.4.2 AC General Purpose IO Specifications | 24 |
| 3.4.3 AC Operational Amplifier Specifications | 25 |
| 3.4.4 AC Analog Mux Bus Specifications | 25 |
| 3.4.5 AC Digital Block Specifications | 25 |
| 3.4.6 AC External Clock Specifications | 27 |
| 3.4.7 AC Programming Specifications | 28 |
| 3.4.8 AC I2C Specifications | 28 |
| 4. Packaging Information | 30 |
| 4.1 Packaging Dimensions | 30 |
| 4.2 Thermal Impedances | 32 |
| 4.3 Solder Reflow Peak Temperature | 33 |
| 5. Ordering Information | 34 |
| 5.1 Ordering Code Definitions | 34 |
| 6. Sales and Service Information | 35 |
| 6.1 Revision History | 35 |
| 6.2 Copyrights and Code Protection | 35 |

1. Pin Information



This chapter describes, lists, and illustrates the CY8C21x34 PSoC device pins and pinout configurations.

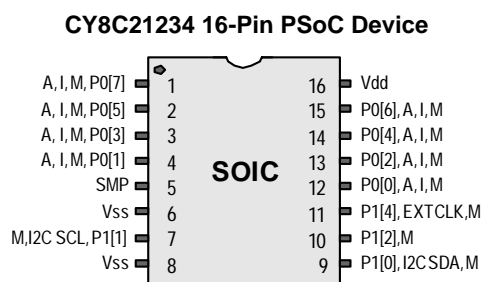
1.1 Pinouts

The CY8C21x34 PSoC device is available in a variety of packages which are listed and illustrated in the following tables. Every port pin (labeled with a "P") is capable of Digital IO and connection to the common analog bus. However, Vss, Vdd, SMP, and XRES are not capable of Digital IO.

1.1.1 16-Pin Part Pinout

Table 1-1. 16-Pin Part Pinout (SOIC)

| Pin No. | Type | | Name | Description |
|---------|---------|--------|-------|--|
| | Digital | Analog | | |
| 1 | IO | I, M | P0[7] | Analog column mux input. |
| 2 | IO | I, M | P0[5] | Analog column mux input. |
| 3 | IO | I, M | P0[3] | Analog column mux input, integrating input. |
| 4 | IO | I, M | P0[1] | Analog column mux input, integrating input. |
| 5 | Power | | SMP | Switch Mode Pump (SMP) connection to required external components. |
| 6 | Power | | Vss | Ground connection. |
| 7 | IO | M | P1[1] | I2C Serial Clock (SCL). |
| 8 | Power | | Vss | Ground connection. |
| 9 | IO | M | P1[0] | I2C Serial Data (SDA). |
| 10 | IO | M | P1[2] | |
| 11 | IO | M | P1[4] | Optional External Clock Input (EXTCLK). |
| 12 | IO | I, M | P0[0] | Analog column mux input. |
| 13 | IO | I, M | P0[2] | Analog column mux input. |
| 14 | IO | I, M | P0[4] | Analog column mux input. |
| 15 | IO | I, M | P0[6] | Analog column mux input. |
| 16 | Power | | Vdd | Supply voltage. |



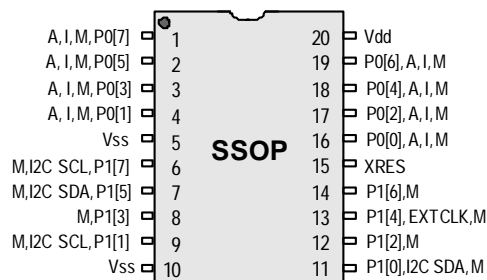
LEGEND A = Analog, I = Input, O = Output, and M = Analog Mux Input.

1.1.2 20-Pin Part Pinout

Table 1-2. 20-Pin Part Pinout (SSOP)

| Pin No. | Type | | Name | Description |
|---------|---------|--------|-------|---|
| | Digital | Analog | | |
| 1 | IO | I, M | P0[7] | Analog column mux input. |
| 2 | IO | I, M | P0[5] | Analog column mux input. |
| 3 | IO | I, M | P0[3] | Analog column mux input, integrating input. |
| 4 | IO | I, M | P0[1] | Analog column mux input, integrating input. |
| 5 | Power | | Vss | Ground connection. |
| 6 | IO | M | P1[7] | I2C Serial Clock (SCL). |
| 7 | IO | M | P1[5] | I2C Serial Data (SDA). |
| 8 | IO | M | P1[3] | |
| 9 | IO | M | P1[1] | I2C Serial Clock (SCL). |
| 10 | Power | | Vss | Ground connection. |
| 11 | IO | M | P1[0] | I2C Serial Data (SDA). |
| 12 | IO | M | P1[2] | |
| 13 | IO | M | P1[4] | Optional External Clock Input (EXT-CLK). |
| 14 | IO | M | P1[6] | |
| 15 | Input | | XRES | Active high external reset with internal pull down. |
| 16 | IO | I, M | P0[0] | Analog column mux input. |
| 17 | IO | I, M | P0[2] | Analog column mux input. |
| 18 | IO | I, M | P0[4] | Analog column mux input. |
| 19 | IO | I, M | P0[6] | Analog column mux input. |
| 20 | Power | | Vdd | Supply voltage. |

CY8C21334 20-Pin PSoC Device



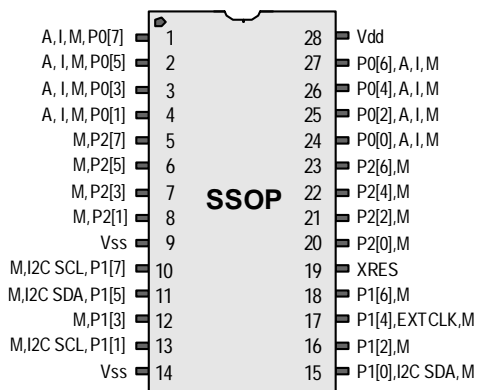
LEGEND A = Analog, I = Input, O = Output, and M = Analog Mux Input.

1.1.3 28-Pin Part Pinout

Table 1-3. 28-Pin Part Pinout (SSOP)

| Pin No. | Type | | Name | Description |
|---------|---------|--------|-------|---|
| | Digital | Analog | | |
| 1 | IO | I, M | P0[7] | Analog column mux input. |
| 2 | IO | I, M | P0[5] | Analog column mux input and column output. |
| 3 | IO | I, M | P0[3] | Analog column mux input and column output, integrating input. |
| 4 | IO | I, M | P0[1] | Analog column mux input, integrating input. |
| 5 | IO | M | P2[7] | |
| 6 | IO | M | P2[5] | |
| 7 | IO | I, M | P2[3] | Direct switched capacitor block input. |
| 8 | IO | I, M | P2[1] | Direct switched capacitor block input. |
| 9 | Power | | Vss | Ground connection. |
| 10 | IO | M | P1[7] | I2C Serial Clock (SCL). |
| 11 | IO | M | P1[5] | I2C Serial Data (SDA). |
| 12 | IO | M | P1[3] | |
| 13 | IO | M | P1[1] | I2C Serial Clock (SCL). |
| 14 | Power | | Vss | Ground connection. |
| 15 | IO | M | P1[0] | I2C Serial Data (SDA). |
| 16 | IO | M | P1[2] | |
| 17 | IO | M | P1[4] | Optional External Clock Input (EXT-CLK). |
| 18 | IO | M | P1[6] | |
| 19 | Input | | XRES | Active high external reset with internal pull down. |
| 20 | IO | I, M | P2[0] | Direct switched capacitor block input. |
| 21 | IO | I, M | P2[2] | Direct switched capacitor block input. |
| 22 | IO | M | P2[4] | |
| 23 | IO | M | P2[6] | |
| 24 | IO | I, M | P0[0] | Analog column mux input. |
| 25 | IO | I, M | P0[2] | Analog column mux input. |
| 26 | IO | I, M | P0[4] | Analog column mux input. |
| 27 | IO | I, M | P0[6] | Analog column mux input. |
| 28 | Power | | Vdd | Supply voltage. |

CY8C21534 28-Pin PSoC Device



LEGEND A: Analog, I: Input, O = Output, and M = Analog Mux Input.

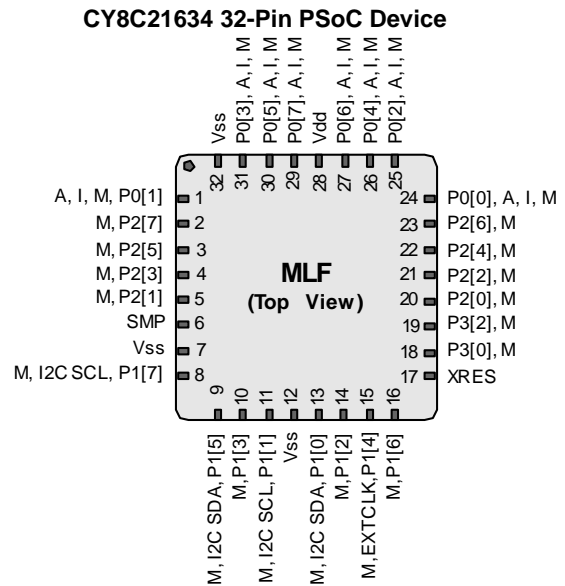
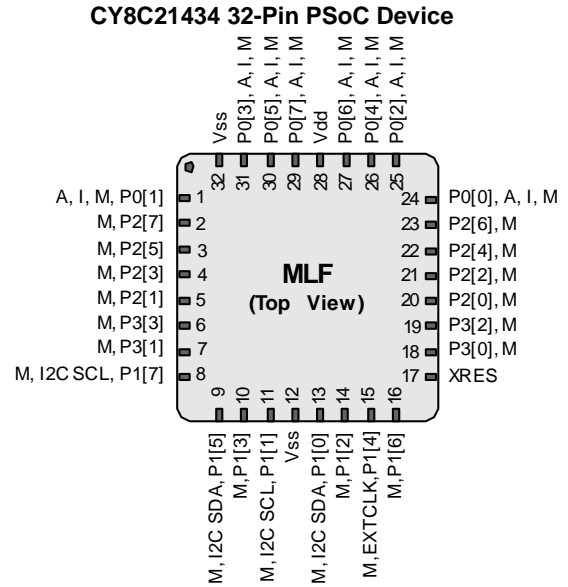
1.1.4 32-Pin Part Pinout

Table 1-4. 32-Pin Part Pinout (MLF*)

| Pin No. | Type | | Name | Description |
|---------|---------|--------|-------|--|
| | Digital | Analog | | |
| 1 | IO | I, M | P0[1] | Analog column mux input, integrating input. |
| 2 | IO | M | P2[7] | |
| 3 | IO | M | P2[5] | |
| 4 | IO | M | P2[3] | |
| 5 | IO | M | P2[1] | |
| 6 | IO | M | P3[3] | In CY8C21434 part. |
| 6 | Power | | SMP | Switch Mode Pump (SMP) connection to required external components in CY8C21634 part. |
| 7 | IO | M | P3[1] | In CY8C21434 part. |
| 7 | Power | | Vss | Ground connection in CY8C21634 part. |
| 8 | IO | M | P1[7] | I2C Serial Clock (SCL). |
| 9 | IO | M | P1[5] | I2C Serial Data (SDA). |
| 10 | IO | M | P1[3] | |
| 11 | IO | M | P1[1] | I2C Serial Clock (SCL). |
| 12 | Power | | Vss | Ground connection. |
| 13 | IO | M | P1[0] | I2C Serial Data (SDA). |
| 14 | IO | M | P1[2] | |
| 15 | IO | M | P1[4] | Optional External Clock Input (EXTCLK). |
| 16 | IO | M | P1[6] | |
| 17 | Input | | XRES | Active high external reset with internal pull down. |
| 18 | IO | M | P3[0] | |
| 19 | IO | M | P3[2] | |
| 20 | IO | M | P2[0] | |
| 21 | IO | M | P2[2] | |
| 22 | IO | M | P2[4] | |
| 23 | IO | M | P2[6] | |
| 24 | IO | I, M | P0[0] | Analog column mux input. |
| 25 | IO | I, M | P0[2] | Analog column mux input. |
| 26 | IO | I, M | P0[4] | Analog column mux input. |
| 27 | IO | I, M | P0[6] | Analog column mux input. |
| 28 | Power | | Vdd | Supply voltage. |
| 29 | IO | I, M | P0[7] | Analog column mux input. |
| 30 | IO | I, M | P0[5] | Analog column mux input. |
| 31 | IO | I, M | P0[3] | Analog column mux input, integrating input. |
| 32 | Power | | Vss | Ground connection. |

LEGEND A = Analog, I = Input, O = Output, and M = Analog Mux Input.

* The MLF package has a center pad that must be connected to ground (Vss).



2. Register Reference



This chapter lists the registers of the CY8C21x34 PSoC device. For detailed register information, reference the *PSoC™ Mixed-Signal Array Technical Reference Manual*.

2.1 Register Conventions

The register conventions specific to this section are listed in the following table.

| Convention | Description |
|------------|------------------------------|
| R | Read register or bit(s) |
| W | Write register or bit(s) |
| L | Logical register or bit(s) |
| C | Clearable register or bit(s) |
| # | Access is bit specific |

2.2 Register Mapping Tables

The PSoC device has a total register address space of 512 bytes. The register space is referred to as IO space and is divided into two banks. The XOI bit in the Flag register (CPU_F) determines which bank the user is currently in. When the XOI bit is set the user is in Bank 1.

Note In the following register mapping tables, blank fields are Reserved and should not be accessed.

Register Map 0 Table: User Space

| Name | Addr (0,Hex) | Access | Name | Addr (0,Hex) | Access | Name | Addr (0,Hex) | Access | Name | Addr (0,Hex) | Access |
|----------|--------------|--------|----------|--------------|--------|----------|--------------|--------|----------|--------------|--------|
| PRT0DR | 00 | RW | | 40 | | ASE10CR0 | 80 | RW | | C0 | |
| PRT0IE | 01 | RW | | 41 | | | 81 | | | C1 | |
| PRT0GS | 02 | RW | | 42 | | | 82 | | | C2 | |
| PRT0DM2 | 03 | RW | | 43 | | | 83 | | | C3 | |
| PRT1DR | 04 | RW | | 44 | | ASE11CR0 | 84 | RW | | C4 | |
| PRT1IE | 05 | RW | | 45 | | | 85 | | | C5 | |
| PRT1GS | 06 | RW | | 46 | | | 86 | | | C6 | |
| PRT1DM2 | 07 | RW | | 47 | | | 87 | | | C7 | |
| PRT2DR | 08 | RW | | 48 | | | 88 | | | C8 | |
| PRT2IE | 09 | RW | | 49 | | | 89 | | | C9 | |
| PRT2GS | 0A | RW | | 4A | | | 8A | | | CA | |
| PRT2DM2 | 0B | RW | | 4B | | | 8B | | | CB | |
| PRT3DR | 0C | RW | | 4C | | | 8C | | | CC | |
| PRT3IE | 0D | RW | | 4D | | | 8D | | | CD | |
| PRT3GS | 0E | RW | | 4E | | | 8E | | | CE | |
| PRT3DM2 | 0F | RW | | 4F | | | 8F | | | CF | |
| | 10 | | | 50 | | | 90 | | CUR_PP | D0 | RW |
| | 11 | | | 51 | | | 91 | | STK_PP | D1 | RW |
| | 12 | | | 52 | | | 92 | | | D2 | |
| | 13 | | | 53 | | | 93 | | IDX_PP | D3 | RW |
| | 14 | | | 54 | | | 94 | | MVR_PP | D4 | RW |
| | 15 | | | 55 | | | 95 | | MVW_PP | D5 | RW |
| | 16 | | | 56 | | | 96 | | I2C_CFG | D6 | RW |
| | 17 | | | 57 | | | 97 | | I2C_SCR | D7 | # |
| | 18 | | | 58 | | | 98 | | I2C_DR | D8 | RW |
| | 19 | | | 59 | | | 99 | | I2C_MSCR | D9 | # |
| | 1A | | | 5A | | | 9A | | INT_CLR0 | DA | RW |
| | 1B | | | 5B | | | 9B | | INT_CLR1 | DB | RW |
| | 1C | | | 5C | | | 9C | | | DC | |
| | 1D | | | 5D | | | 9D | | INT_CLR3 | DD | RW |
| | 1E | | | 5E | | | 9E | | INT_MSK3 | DE | RW |
| | 1F | | | 5F | | | 9F | | | DF | |
| DBB00DR0 | 20 | # | AMX_IN | 60 | RW | | A0 | | INT_MSK0 | E0 | RW |
| DBB00DR1 | 21 | W | AMUXCFG | 61 | RW | | A1 | | INT_MSK1 | E1 | RW |
| DBB00DR2 | 22 | RW | PWM_CR | 62 | RW | | A2 | | INT_VC | E2 | RC |
| DBB00CR0 | 23 | # | | 63 | | | A3 | | RES_WDT | E3 | W |
| DBB01DR0 | 24 | # | CMP_CR0 | 64 | # | | A4 | | | E4 | |
| DBB01DR1 | 25 | W | | 65 | | | A5 | | | E5 | |
| DBB01DR2 | 26 | RW | CMP_CR1 | 66 | RW | | A6 | | DEC_CR0 | E6 | RW |
| DBB01CR0 | 27 | # | | 67 | | | A7 | | DEC_CR1 | E7 | RW |
| DCB02DR0 | 28 | # | ADC0_CR | 68 | # | | A8 | | | E8 | |
| DCB02DR1 | 29 | W | ADC1_CR | 69 | # | | A9 | | | E9 | |
| DCB02DR2 | 2A | RW | | 6A | | | AA | | | EA | |
| DCB02CR0 | 2B | # | | 6B | | | AB | | | EB | |
| DCB03DR0 | 2C | # | TMP0_DR | 6C | RW | | AC | | | EC | |
| DCB03DR1 | 2D | W | TMP1_DR | 6D | RW | | AD | | | ED | |
| DCB03DR2 | 2E | RW | TMP2_DR | 6E | RW | | AE | | | EE | |
| DCB03CR0 | 2F | # | TMP3_DR | 6F | RW | | AF | | | EF | |
| | 30 | | | 70 | | RDI0RI | B0 | RW | | F0 | |
| | 31 | | | 71 | | RDI0SYN | B1 | RW | | F1 | |
| | 32 | | ACE00CR1 | 72 | RW | RDI0IS | B2 | RW | | F2 | |
| | 33 | | ACE00CR2 | 73 | RW | RDI0LT0 | B3 | RW | | F3 | |
| | 34 | | | 74 | | RDI0LT1 | B4 | RW | | F4 | |
| | 35 | | | 75 | | RDI0RO0 | B5 | RW | | F5 | |
| | 36 | | ACE01CR1 | 76 | RW | RDI0RO1 | B6 | RW | | F6 | |
| | 37 | | ACE01CR2 | 77 | RW | | B7 | | CPU_F | F7 | RL |
| | 38 | | | 78 | | | B8 | | | F8 | |
| | 39 | | | 79 | | | B9 | | | F9 | |
| | 3A | | | 7A | | | BA | | | FA | |
| | 3B | | | 7B | | | BB | | | FB | |
| | 3C | | | 7C | | | BC | | | FC | |
| | 3D | | | 7D | | | BD | | DAC_D | FD | RW |
| | 3E | | | 7E | | | BE | | CPU_SCR1 | FE | # |
| | 3F | | | 7F | | | BF | | CPU_SCR0 | FF | # |

Blank fields are Reserved and should not be accessed.

Access is bit specific.

Register Map 1 Table: Configuration Space

| Name | Addr (1,Hex) | Access | Name | Addr (1,Hex) | Access | Name | Addr (1,Hex) | Access | Name | Addr (1,Hex) | Access |
|---------|--------------|--------|-----------|--------------|--------|----------|--------------|--------|-----------|--------------|--------|
| PRT0DM0 | 00 | RW | | 40 | | ASE10CR0 | 80 | RW | | C0 | |
| PRT0DM1 | 01 | RW | | 41 | | | 81 | | | C1 | |
| PRT0IC0 | 02 | RW | | 42 | | | 82 | | | C2 | |
| PRT0IC1 | 03 | RW | | 43 | | | 83 | | | C3 | |
| PRT1DM0 | 04 | RW | | 44 | | ASE11CR0 | 84 | RW | | C4 | |
| PRT1DM1 | 05 | RW | | 45 | | | 85 | | | C5 | |
| PRT1IC0 | 06 | RW | | 46 | | | 86 | | | C6 | |
| PRT1IC1 | 07 | RW | | 47 | | | 87 | | | C7 | |
| PRT2DM0 | 08 | RW | | 48 | | | 88 | | | C8 | |
| PRT2DM1 | 09 | RW | | 49 | | | 89 | | | C9 | |
| PRT2IC0 | 0A | RW | | 4A | | | 8A | | | CA | |
| PRT2IC1 | 0B | RW | | 4B | | | 8B | | | CB | |
| PRT3DM0 | 0C | RW | | 4C | | | 8C | | | CC | |
| PRT3DM1 | 0D | RW | | 4D | | | 8D | | | CD | |
| PRT3IC0 | 0E | RW | | 4E | | | 8E | | | CE | |
| PRT3IC1 | 0F | RW | | 4F | | | 8F | | | CF | |
| | 10 | | | 50 | | | 90 | | GDI_O_IN | D0 | RW |
| | 11 | | | 51 | | | 91 | | GDI_E_IN | D1 | RW |
| | 12 | | | 52 | | | 92 | | GDI_O_OU | D2 | RW |
| | 13 | | | 53 | | | 93 | | GDI_E_OU | D3 | RW |
| | 14 | | | 54 | | | 94 | | | D4 | |
| | 15 | | | 55 | | | 95 | | | D5 | |
| | 16 | | | 56 | | | 96 | | | D6 | |
| | 17 | | | 57 | | | 97 | | | D7 | |
| | 18 | | | 58 | | | 98 | | MUX_CR0 | D8 | RW |
| | 19 | | | 59 | | | 99 | | MUX_CR1 | D9 | RW |
| | 1A | | | 5A | | | 9A | | MUX_CR2 | DA | RW |
| | 1B | | | 5B | | | 9B | | MUX_CR3 | DB | RW |
| | 1C | | | 5C | | | 9C | | | DC | |
| | 1D | | | 5D | | | 9D | | OSC_GO_EN | DD | RW |
| | 1E | | | 5E | | | 9E | | OSC_CR4 | DE | RW |
| | 1F | | | 5F | | | 9F | | OSC_CR3 | DF | RW |
| DBB00FN | 20 | RW | CLK_CR0 | 60 | RW | | A0 | | OSC_CR0 | E0 | RW |
| DBB00IN | 21 | RW | CLK_CR1 | 61 | RW | | A1 | | OSC_CR1 | E1 | RW |
| DBB00OU | 22 | RW | ABF_CR0 | 62 | RW | | A2 | | OSC_CR2 | E2 | RW |
| | 23 | | AMD_CR0 | 63 | RW | | A3 | | VLT_CR | E3 | RW |
| DBB01FN | 24 | RW | CMP_GO_EN | 64 | RW | | A4 | | VLT_CMP | E4 | R |
| DBB01IN | 25 | RW | | 65 | | | A5 | | ADC0_TR | E5 | RW |
| DBB01OU | 26 | RW | AMD_CR1 | 66 | RW | | A6 | | ADC1_TR | E6 | RW |
| | 27 | | ALT_CR0 | 67 | RW | | A7 | | | E7 | |
| DCB02FN | 28 | RW | | 68 | | | A8 | | IMO_TR | E8 | W |
| DCB02IN | 29 | RW | | 69 | | | A9 | | ILO_TR | E9 | W |
| DCB02OU | 2A | RW | | 6A | | | AA | | BDG_TR | EA | RW |
| | 2B | | CLK_CR3 | 6B | RW | | AB | | ECO_TR | EB | W |
| DCB03FN | 2C | RW | TMP0_DR | 6C | RW | | AC | | | EC | |
| DCB03IN | 2D | RW | TMP1_DR | 6D | RW | | AD | | | ED | |
| DCB03OU | 2E | RW | TMP2_DR | 6E | RW | | AE | | | EE | |
| | 2F | | TMP3_DR | 6F | RW | | AF | | | EF | |
| | 30 | | | 70 | | RDI0RI | B0 | RW | | F0 | |
| | 31 | | | 71 | | RDI0SYN | B1 | RW | | F1 | |
| | 32 | | ACE00CR1 | 72 | RW | RDI0IS | B2 | RW | | F2 | |
| | 33 | | ACE00CR2 | 73 | RW | RDI0LT0 | B3 | RW | | F3 | |
| | 34 | | | 74 | | RDI0LT1 | B4 | RW | | F4 | |
| | 35 | | | 75 | | RDI0RO0 | B5 | RW | | F5 | |
| | 36 | | ACE01CR1 | 76 | RW | RDI0RO1 | B6 | RW | | F6 | |
| | 37 | | ACE01CR2 | 77 | RW | | B7 | | CPU_F | F7 | RL |
| | 38 | | | 78 | | | B8 | | | F8 | |
| | 39 | | | 79 | | | B9 | | | F9 | |
| | 3A | | | 7A | | | BA | | FLS_PR1 | FA | RW |
| | 3B | | | 7B | | | BB | | | FB | |
| | 3C | | | 7C | | | BC | | | FC | |
| | 3D | | | 7D | | | BD | | DAC_CR | FD | RW |
| | 3E | | | 7E | | | BE | | CPU_SCR1 | FE | # |
| | 3F | | | 7F | | | BF | | CPU_SCR0 | FF | # |

Blank fields are Reserved and should not be accessed.

Access is bit specific.

3. Electrical Specifications



This chapter presents the DC and AC electrical specifications of the CY8C21x34 PSoC device. For the most up to date electrical specifications, confirm that you have the most recent data sheet by going to the web at <http://www.cypress.com/psoc>.

Specifications are valid for $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ and $T_J \leq 100^{\circ}\text{C}$ as specified, except where noted.

Refer to Table 3-14 for the electrical specifications on the internal main oscillator (IMO) using SLIMO mode.

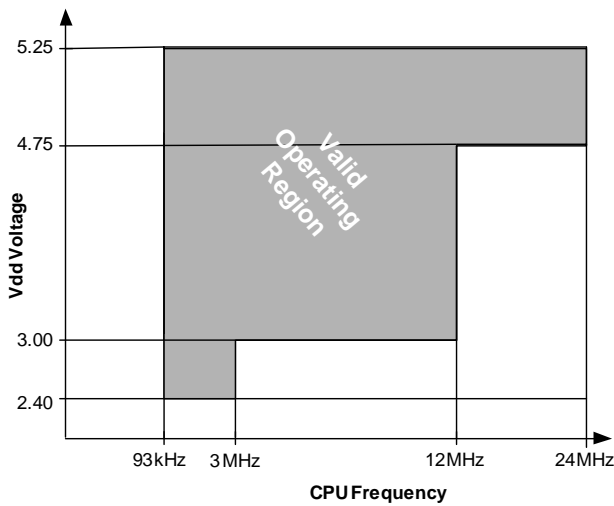


Figure 3-1a. Voltage versus CPU Frequency

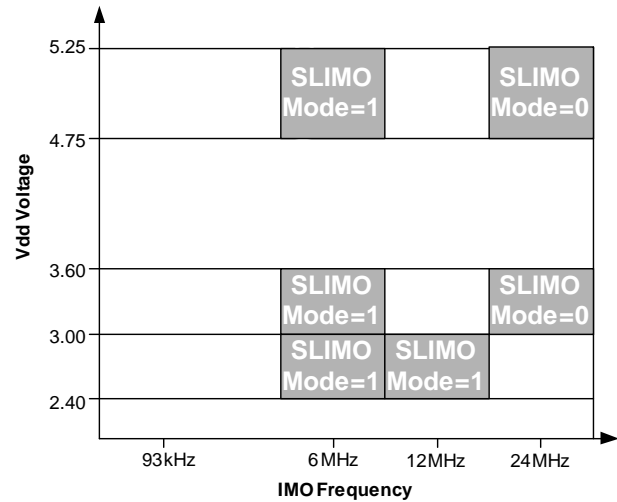


Figure 3-1b. IMO Frequency Trim Options

The following table lists the units of measure that are used in this chapter.

Table 3-1: Units of Measure

| Symbol | Unit of Measure | Symbol | Unit of Measure |
|--------|-----------------------------|--------|-------------------------------|
| °C | degree Celsius | μW | microwatts |
| dB | decibels | mA | milli-ampere |
| fF | femto farad | ms | milli-second |
| Hz | hertz | mV | milli-volts |
| KB | 1024 bytes | nA | nanoampere |
| Kbit | 1024 bits | ns | nanosecond |
| kHz | kilohertz | nV | nanovolts |
| kΩ | kilohm | Ω | ohm |
| MHz | megahertz | pA | picoampere |
| MΩ | megaohm | pF | picofarad |
| μA | microampere | pp | peak-to-peak |
| μF | microfarad | ppm | parts per million |
| μH | microhenry | ps | picosecond |
| μs | microsecond | sps | samples per second |
| μV | microvolts | σ | sigma: one standard deviation |
| μVrms | microvolts root-mean-square | V | volts |

3.1 Absolute Maximum Ratings

Table 3-2. Absolute Maximum Ratings

| Symbol | Description | Min | Typ | Max | Units | Notes |
|------------------|---|-----------------------|-----|-----------------------|-------|--|
| T _{STG} | Storage Temperature | -55 | – | +100 | °C | Higher storage temperatures will reduce data retention time. |
| T _A | Ambient Temperature with Power Applied | -40 | – | +85 | °C | |
| V _{DD} | Supply Voltage on V _{DD} Relative to V _{SS} | -0.5 | – | +6.0 | V | |
| V _{IO} | DC Input Voltage | V _{SS} - 0.5 | – | V _{DD} + 0.5 | V | |
| V _{IOZ} | DC Voltage Applied to Tri-state | V _{SS} - 0.5 | – | V _{DD} + 0.5 | V | |
| I _{MIO} | Maximum Current into any Port Pin | -25 | – | +50 | mA | |
| ESD | Electro Static Discharge Voltage | 2000 | – | – | V | Human Body Model ESD. |
| LU | Latch-up Current | – | – | 200 | mA | |

3.2 Operating Temperature

Table 3-3. Operating Temperature

| Symbol | Description | Min | Typ | Max | Units | Notes |
|----------------|----------------------|-----|-----|------|-------|--|
| T _A | Ambient Temperature | -40 | – | +85 | °C | |
| T _J | Junction Temperature | -40 | – | +100 | °C | The temperature rise from ambient to junction is package specific. See "Thermal Impedances" on page 32. The user must limit the power consumption to comply with this requirement. |

3.3 DC Electrical Characteristics

3.3.1 DC Chip-Level Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 2.4V to 3.0V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C and are for design guidance only.

Table 3-4. DC Chip-Level Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|--------------------|---|--------------------------|------------------|--------------------------|-------|---|
| V _{DD} | Supply Voltage | 2.40 | – | 5.25 | V | See table titled "DC POR and LVD Specifications" on page 20. |
| I _{DD} | Supply Current, IMO = 24 MHz | – | 3 | 4 | mA | Conditions are V _{DD} = 5.0V, T _A = 25°C, CPU = 3 MHz, clock doubler disabled. VC1 = 1.5 MHz, VC2 = 93.75 kHz, VC3 = 0.366 kHz. |
| I _{DD3} | Supply Current, IMO = 6 MHz using SLIMO mode. | – | 1.2 | 2 | mA | Conditions are V _{DD} = 3.3V, T _A = 25°C, CPU = 3 MHz, clock doubler disabled. VC1 = 375 kHz, VC2 = 23.4 kHz, VC3 = 0.091 kHz. |
| I _{DD27} | Supply Current, IMO = 6 MHz using SLIMO mode. | – | 1.1 | 1.5 | mA | Conditions are V _{DD} = 2.55V, T _A = 25°C, CPU = 3 MHz, clock doubler disabled. VC1 = 375 kHz, VC2 = 23.4 kHz, VC3 = 0.091 kHz. |
| I _{SB27} | Sleep (Mode) Current with POR, LVD, Sleep Timer, WDT, and internal slow oscillator active. Mid temperature range. | – | 2.5 | 3. | μA | V _{DD} = 2.55V, 0°C ≤ T _A ≤ 40°C. |
| I _{SB} | Sleep (Mode) Current with POR, LVD, Sleep Timer, WDT, and internal slow oscillator active. | – | 2.8 | 5 | μA | V _{DD} = 3.3V, -40°C ≤ T _A ≤ 85°C. |
| V _{REF} | Reference Voltage (Bandgap) | 1.28 | 1.30 | 1.32 | V | Trimmed for appropriate V _{DD} . V _{DD} = 3.0V to 5.25V. |
| V _{REF27} | Reference Voltage (Bandgap) | 1.16 | 1.30 | 1.33 | V | Trimmed for appropriate V _{DD} . V _{DD} = 2.4V to 3.0V. |
| AGND | Analog Ground | V _{REF} - 0.003 | V _{REF} | V _{REF} + 0.003 | V | |

3.3.2 DC General Purpose IO Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 2.4V to 3.0V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, and 2.7V at 25°C and are for design guidance only.

Table 3-5. 5V and 3.3V DC GPIO Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|------------------|-----------------------------------|-----------------------|-----|------|------------|--|
| R _{PU} | Pull-up Resistor | 4 | 5.6 | 8 | k Ω | |
| R _{PD} | Pull-down Resistor | 4 | 5.6 | 8 | k Ω | |
| V _{OH} | High Output Level | V _{dd} - 1.0 | – | – | V | IOH = 10 mA, V _{dd} = 4.75 to 5.25V (8 total loads, 4 on even port pins (for example, P0[2], P1[4]), 4 on odd port pins (for example, P0[3], P1[5])). |
| V _{OL} | Low Output Level | – | – | 0.75 | V | IOL = 25 mA, V _{dd} = 4.75 to 5.25V (8 total loads, 4 on even port pins (for example, P0[2], P1[4]), 4 on odd port pins (for example, P0[3], P1[5])). |
| V _{IL} | Input Low Level | – | – | 0.8 | V | V _{dd} = 3.0 to 5.25. |
| V _{IH} | Input High Level | 2.1 | – | – | V | V _{dd} = 3.0 to 5.25. |
| V _H | Input Hysteresis | – | 60 | – | mV | |
| I _{IL} | Input Leakage (Absolute Value) | – | 1 | – | nA | Gross tested to 1 μA . |
| C _{IN} | Capacitive Load on Pins as Input | – | 3.5 | 10 | pF | Package and pin dependent. Temp = 25°C . |
| C _{OUT} | Capacitive Load on Pins as Output | – | 3.5 | 10 | pF | Package and pin dependent. Temp = 25°C . |

Table 3-6. 2.7V DC GPIO Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|------------------|-----------------------------------|-----------------------|-----|------|------------|--|
| R _{PU} | Pull-up Resistor | 4 | 5.6 | 8 | k Ω | |
| R _{PD} | Pull-down Resistor | 4 | 5.6 | 8 | k Ω | |
| V _{OH} | High Output Level | V _{dd} - 0.4 | – | – | V | IOH = 2.5 mA (6.25 Typ), V _{dd} = 2.4 to 3.0V (16 mA maximum, 50 mA Typ combined IOH budget). |
| V _{OL} | Low Output Level | – | – | 0.75 | V | IOL = 10 mA, V _{dd} = 2.4 to 3.0V (90 mA maximum combined IOL budget). |
| V _{IL} | Input Low Level | – | – | 0.75 | V | V _{dd} = 2.4 to 3.0. |
| V _{IH} | Input High Level | 2.0 | – | – | V | V _{dd} = 2.4 to 3.0. |
| V _H | Input Hysteresis | – | 90 | – | mV | |
| I _{IL} | Input Leakage (Absolute Value) | – | 1 | – | nA | Gross tested to 1 μA . |
| C _{IN} | Capacitive Load on Pins as Input | – | 3.5 | 10 | pF | Package and pin dependent. Temp = 25°C . |
| C _{OUT} | Capacitive Load on Pins as Output | – | 3.5 | 10 | pF | Package and pin dependent. Temp = 25°C . |

3.3.3 DC Operational Amplifier Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 2.4V to 3.0V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C and are for design guidance only.

Table 3-7. 5V DC Operational Amplifier Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|---------------------|--|-----|-----|---------------------|--------------------------------|--|
| V _{OSOA} | Input Offset Voltage (absolute value) | – | 2.5 | 15 | mV | |
| TCV _{OSOA} | Average Input Offset Voltage Drift | – | 10 | – | $\mu\text{V}/^{\circ}\text{C}$ | |
| I _{EBOA} | Input Leakage Current (Port 0 Analog Pins) | – | 200 | – | pA | Gross tested to 1 μA . |
| C _{INOA} | Input Capacitance (Port 0 Analog Pins) | – | 4.5 | 9.5 | pF | Package and pin dependent. Temp = 25°C . |
| V _{CMOA} | Common Mode Voltage Range | 0.0 | – | V _{dd} - 1 | V | |
| G _{OLOA} | Open Loop Gain | – | 80 | – | dB | |
| I _{SOA} | Amplifier Supply Current | – | 10 | 30 | μA | |

Table 3-8. 3.3V DC Operational Amplifier Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|---------------------|--|-----|-----|---------------------|--------------------------------|--|
| V _{OSOA} | Input Offset Voltage (absolute value) | – | 2.5 | 15 | mV | |
| TCV _{OSOA} | Average Input Offset Voltage Drift | – | 10 | – | $\mu\text{V}/^{\circ}\text{C}$ | |
| I _{EBOA} | Input Leakage Current (Port 0 Analog Pins) | – | 200 | – | pA | Gross tested to 1 μA . |
| C _{INOA} | Input Capacitance (Port 0 Analog Pins) | – | 4.5 | 9.5 | pF | Package and pin dependent. Temp = 25°C . |
| V _{CMOA} | Common Mode Voltage Range | 0 | – | V _{dd} - 1 | V | |
| G _{OLOA} | Open Loop Gain | – | 80 | – | dB | |
| I _{SOA} | Amplifier Supply Current | – | 10 | 30 | μA | |

Table 3-9. 2.7V DC Operational Amplifier Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|---------------------|--|-----|-----|---------------------|--------------------------------|--|
| V _{OSOA} | Input Offset Voltage (absolute value) | – | 2.5 | 15 | mV | |
| TCV _{OSOA} | Average Input Offset Voltage Drift | – | 10 | – | $\mu\text{V}/^{\circ}\text{C}$ | |
| I _{EBOA} | Input Leakage Current (Port 0 Analog Pins) | – | 200 | – | pA | Gross tested to 1 μA . |
| C _{INOA} | Input Capacitance (Port 0 Analog Pins) | – | 4.5 | 9.5 | pF | Package and pin dependent. Temp = 25°C . |
| V _{CMOA} | Common Mode Voltage Range | 0 | – | V _{dd} - 1 | V | |
| G _{OLOA} | Open Loop Gain | – | 80 | – | dB | |
| I _{SOA} | Amplifier Supply Current | – | 10 | 30 | μA | |

3.3.4 DC Switch Mode Pump Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 2.4V to 3.0V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C and are for design guidance only.

Table 3-10. DC Switch Mode Pump (SMP) Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|----------------------------------|---|-------------|-------------|-------------|-----------------|---|
| V _{PUMP5V} | 5V Output Voltage from Pump | 4.75 | 5.0 | 5.25 | V | Configuration of footnote. ^a Average, neglecting ripple. SMP trip voltage is set to 5.0V. |
| V _{PUMP3V} | 3.3V Output Voltage from Pump | 3.00 | 3.25 | 3.60 | V | Configuration of footnote. ^a Average, neglecting ripple. SMP trip voltage is set to 3.25V. |
| V _{PUMP2V} | 2.6V Output Voltage from Pump | 2.45 | 2.55 | 2.80 | V | Configuration of footnote. ^a Average, neglecting ripple. SMP trip voltage is set to 2.55V. |
| I _{PUMP} | Available Output Current V _{BAT} = 1.8V, V _{PUMP} = 5.0V V _{BAT} = 1.5V, V _{PUMP} = 3.25V V _{BAT} = 1.3V, V _{PUMP} = 2.55V | 5 8 8 | – – – | – – – | mA mA mA | Configuration of footnote. ^a SMP trip voltage is set to 5.0V. SMP trip voltage is set to 3.25V. SMP trip voltage is set to 2.55V. |
| V _{BAT5V} | Input Voltage Range from Battery | 1.8 | – | 5.0 | V | Configuration of footnote. ^a SMP trip voltage is set to 5.0V. |
| V _{BAT3V} | Input Voltage Range from Battery | 1.0 | – | 3.3 | V | Configuration of footnote. ^a SMP trip voltage is set to 3.25V. |
| V _{BAT2V} | Input Voltage Range from Battery | 1.0 | – | 2.8 | V | Configuration of footnote. ^a SMP trip voltage is set to 2.55V. |
| V _{BATSTART} | Minimum Input Voltage from Battery to Start Pump | 1.2 | – | – | V | Configuration of footnote. ^a $0^{\circ}\text{C} \leq T_A \leq 100$. 1.25V at $T_A = -40^{\circ}\text{C}$. |
| $\Delta V_{\text{PUMP_Line}}$ | Line Regulation (over V _i range) | – | 5 | – | %V _O | Configuration of footnote. ^a V _O is the "V _{dd} Value for PUMP Trip" specified by the VM[2:0] setting in the DC POR and LVD Specification, Table 3-12 on page 20 . |
| $\Delta V_{\text{PUMP_Load}}$ | Load Regulation | – | 5 | – | %V _O | Configuration of footnote. ^a V _O is the "V _{dd} Value for PUMP Trip" specified by the VM[2:0] setting in the DC POR and LVD Specification, Table 3-12 on page 20 . |
| $\Delta V_{\text{PUMP_Ripple}}$ | Output Voltage Ripple (depends on cap/load) | – | 100 | – | mVpp | Configuration of footnote. ^a Load is 5 mA. |
| E ₃ | Efficiency | 35 | 50 | – | % | Configuration of footnote. ^a Load is 5 mA. SMP trip voltage is set to 3.25V. |
| E ₂ | Efficiency | 35 | 80 | – | % | For I load = 1mA, V _{PUMP} = 2.55V, V _{BAT} = 1.3V, 10 uH inductor, 1 uF capacitor, and Schottky diode. |
| F _{PUMP} | Switching Frequency | – | 1.3 | – | MHz | |
| DC _{PUMP} | Switching Duty Cycle | – | 50 | – | % | |

a. L₁ = 2 μH inductor, C₁ = 10 μF capacitor, D₁ = Schottky diode. See Figure 3-2.

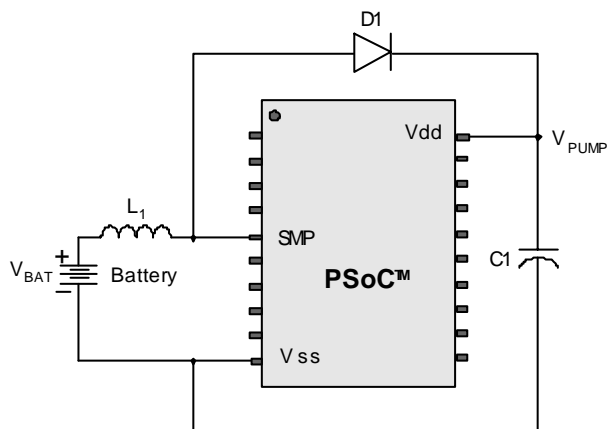


Figure 3-2. Basic Switch Mode Pump Circuit

3.3.5 DC Analog Mux Bus Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 2.4V to 3.0V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C and are for design guidance only.

Table 3-11. DC Analog Mux Bus Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|------------------|--|-----|-----|------------|----------------------|---|
| R _{SW} | Switch Resistance to Common Analog Bus | – | – | 400 800 | Ω Ω | V _{dd} ≥ 2.7V 2.4V ≤ V _{dd} ≤ 2.7V |
| R _{VDD} | Resistance of Initialization Switch to V _{dd} | – | – | 800 | Ω | |

3.3.6 DC POR and LVD Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 2.4V to 3.0V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C and are for design guidance only.

Table 3-12. DC POR and LVD Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|--------------------|--|------|------|-------------------|-------|--|
| V _{PPOR0} | V _{dd} Value for PPOR Trip PORLEV[1:0] = 00b | | 2.36 | 2.40 | V | V _{dd} must be greater than or equal to 2.5V during startup, reset from the XRES pin, or reset from Watchdog. |
| V _{PPOR1} | PORLEV[1:0] = 01b | – | 2.82 | 2.95 | V | |
| V _{PPOR2} | PORLEV[1:0] = 10b | | 4.55 | 4.70 | V | |
| V _{LVD0} | V _{dd} Value for LVD Trip VM[2:0] = 000b | 2.40 | 2.45 | 2.51 ^a | V | |
| V _{LVD1} | VM[2:0] = 001b | 2.85 | 2.92 | 2.99 ^b | V | |
| V _{LVD2} | VM[2:0] = 010b | 2.95 | 3.02 | 3.09 | V | |
| V _{LVD3} | VM[2:0] = 011b | 3.06 | 3.13 | 3.20 | V | |
| V _{LVD4} | VM[2:0] = 100b | 4.37 | 4.48 | 4.55 | V | |
| V _{LVD5} | VM[2:0] = 101b | 4.50 | 4.64 | 4.75 | V | |
| V _{LVD6} | VM[2:0] = 110b | 4.62 | 4.73 | 4.83 | V | |
| V _{LVD7} | VM[2:0] = 111b | 4.71 | 4.81 | 4.95 | V | |
| V _{PUMP0} | V _{dd} Value for PUMP Trip VM[2:0] = 000b | 2.45 | 2.55 | 2.62 ^c | V | |
| V _{PUMP1} | VM[2:0] = 001b | 2.96 | 3.02 | 3.09 | V | |
| V _{PUMP2} | VM[2:0] = 010b | 3.03 | 3.10 | 3.16 | V | |
| V _{PUMP3} | VM[2:0] = 011b | 3.18 | 3.25 | 3.32 ^d | V | |
| V _{PUMP4} | VM[2:0] = 100b | 4.54 | 4.64 | 4.74 | V | |
| V _{PUMP5} | VM[2:0] = 101b | 4.62 | 4.73 | 4.83 | V | |
| V _{PUMP6} | VM[2:0] = 110b | 4.71 | 4.82 | 4.92 | V | |
| V _{PUMP7} | VM[2:0] = 111b | 4.89 | 5.00 | 5.12 | V | |

- Always greater than 50 mV above V_{PPOR} (PORLEV = 00) for falling supply.
- Always greater than 50 mV above V_{PPOR} (PORLEV = 01) for falling supply.
- Always greater than 50 mV above V_{LVD0}.
- Always greater than 50 mV above V_{LVD3}.

3.3.7 DC Programming Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 2.4V to 3.0V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C and are for design guidance only.

Table 3-13. DC Programming Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|-----------|---|-----------|-----|------------|-------|--------------------------------------|
| VddIWRITE | Supply Voltage for Flash Write Operations | 2.70 | – | – | V | |
| IDDP | Supply Current During Programming or Verify | – | 5 | 25 | mA | |
| VILP | Input Low Voltage During Programming or Verify | – | – | 0.8 | V | |
| VIHP | Input High Voltage During Programming or Verify | 2.2 | – | – | V | |
| IILP | Input Current when Applying Vilp to P1[0] or P1[1] During Programming or Verify | – | – | 0.2 | mA | Driving internal pull-down resistor. |
| IIHP | Input Current when Applying Vihp to P1[0] or P1[1] During Programming or Verify | – | – | 1.5 | mA | Driving internal pull-down resistor. |
| VOLV | Output Low Voltage During Programming or Verify | – | – | Vss + 0.75 | V | |
| VOHV | Output High Voltage During Programming or Verify | Vdd - 1.0 | – | Vdd | V | |
| FlashENPB | Flash Endurance (per block) | 50,000 | – | – | – | Erase/write cycles per block. |
| FlashENT | Flash Endurance (total) ^a | 1,800,000 | – | – | – | Erase/write cycles. |
| FlashDR | Flash Data Retention | 10 | – | – | Years | |

- a. A maximum of 36 x 50,000 block endurance cycles is allowed. This may be balanced between operations on 36x1 blocks of 50,000 maximum cycles each, 36x2 blocks of 25,000 maximum cycles each, or 36x4 blocks of 12,500 maximum cycles each (to limit the total number of cycles to 36x50,000 and that no single block ever sees more than 50,000 cycles).

For the full industrial range, the user must employ a temperature sensor user module (FlashTemp) and feed the result to the temperature argument before writing. Refer to the Flash APIs Application Note AN2015 at <http://www.cypress.com> under Application Notes for more information.

3.4 AC Electrical Characteristics

3.4.1 AC Chip-Level Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 2.4V to 3.0V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C and are for design guidance only.

Table 3-14. 5V and 3.3V AC Chip-Level Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|------------|---|------|------|-----------------------|-------|---|
| FIMO24 | Internal Main Oscillator Frequency for 24 MHz | 23.4 | 24 | 24.6 ^{a,b,c} | MHz | Trimmed for 5V or 3.3V operation using factory trim values. See Figure 3-1b on page 15. SLIMO mode = 0. |
| FIMO6 | Internal Main Oscillator Frequency for 6 MHz | 5.75 | 6 | 6.35 ^{a,b,c} | MHz | Trimmed for 5V or 3.3V operation using factory trim values. See Figure 3-1b on page 15. SLIMO mode = 1. |
| FCPU1 | CPU Frequency (5V Nominal) | 0.93 | 24 | 24.6 ^{a,b} | MHz | 24 MHz only for SLIMO mode = 0. |
| FCPU2 | CPU Frequency (3.3V Nominal) | 0.93 | 12 | 12.3 ^{b,c} | MHz | |
| FBLK5 | Digital PSoC Block Frequency (5V Nominal) | 0 | 48 | 49.2 ^{a,b,d} | MHz | Refer to the AC Digital Block Specifications below. |
| FBLK33 | Digital PSoC Block Frequency (3.3V Nominal) | 0 | 24 | 24.6 ^{b,d} | MHz | |
| F32K1 | Internal Low Speed Oscillator Frequency | 15 | 32 | 64 | kHz | |
| Jitter32k | 32 kHz Period Jitter | – | 100 | 200 | ns | |
| TXRST | External Reset Pulse Width | 10 | – | – | μs | |
| DC24M | 24 MHz Duty Cycle | 40 | 50 | 60 | % | |
| Step24M | 24 MHz Trim Step Size | – | 50 | – | kHz | |
| Fout48M | 48 MHz Output Frequency | 46.8 | 48.0 | 49.2 ^{a,c} | MHz | Trimmed. Utilizing factory trim values. |
| Jitter24M1 | 24 MHz Period Jitter (IMO) | – | 600 | – | ps | |
| FMAX | Maximum frequency of signal on row input or row output. | – | – | 12.3 | MHz | |
| TRAMP | Supply Ramp Time | 0 | – | – | μs | |

- 4.75V < V_{dd} < 5.25V.
- Accuracy derived from Internal Main Oscillator with appropriate trim for V_{dd} range.
- 3.0V < V_{dd} < 3.6V. See Application Note AN2012 "Adjusting PSoC Microcontroller Trims for Dual Voltage-Range Operation" for information on trimming for operation at 3.3V.
- See the individual user module data sheets for information on maximum frequencies for user modules.

Table 3-15. 2.7V AC Chip-Level Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|-----------|---|-------|-----|-----------------------|-------|---|
| FIMO12 | Internal Main Oscillator Frequency for 12 MHz | 11.5 | 12 | 12.7 ^{a,b,c} | MHz | Trimmed for 2.7V operation using factory trim values. See Figure 3-1b on page 15. SLIMO mode = 1. |
| FIMO6 | Internal Main Oscillator Frequency for 6 MHz | 5.75 | 6 | 6.35 ^{a,b,c} | MHz | Trimmed for 2.7V operation using factory trim values. See Figure 3-1b on page 15. SLIMO mode = 1. |
| FCPU1 | CPU Frequency (2.7V Nominal) | 0.093 | 3 | 3.15 ^{a,b} | MHz | 24 MHz only for SLIMO mode = 0. |
| FBLK27 | Digital PSoC Block Frequency (2.7V Nominal) | 0 | 12 | 12.5 ^{a,b,c} | MHz | Refer to the AC Digital Block Specifications below. |
| F32K1 | Internal Low Speed Oscillator Frequency | 8 | 32 | 96 | kHz | |
| Jitter32k | 32 kHz Period Jitter | – | 150 | 200 | ns | |
| TXRST | External Reset Pulse Width | 10 | – | – | μs | |
| FMAX | Maximum frequency of signal on row input or row output. | – | – | 12.3 | MHz | |
| TRAMP | Supply Ramp Time | 0 | – | – | μs | |

- 2.4V < V_{dd} < 3.0V.
- Accuracy derived from Internal Main Oscillator with appropriate trim for V_{dd} range.
- See Application Note AN2012 "Adjusting PSoC Microcontroller Trims for Dual Voltage-Range Operation" for information on maximum frequency for user modules.

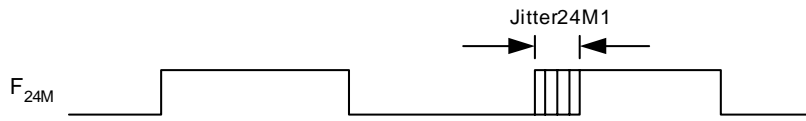


Figure 3-3. 24 MHz Period Jitter (IMO) Timing Diagram

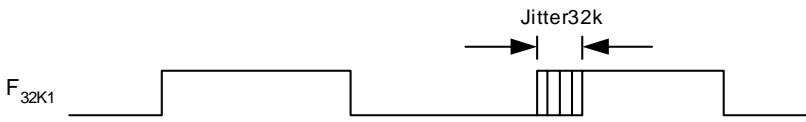


Figure 3-4. 32 kHz Period Jitter (ILO) Timing Diagram

3.4.2 AC General Purpose IO Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 2.4V to 3.0V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C and are for design guidance only.

Table 3-16. 5V and 3.3V AC GPIO Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|--------------------|--|-----|-----|-----|-------|-------------------------------|
| F _{GPIO} | GPIO Operating Frequency | 0 | – | 12 | MHz | Normal Strong Mode |
| T _{RiseF} | Rise Time, Normal Strong Mode, Cload = 50 pF | 3 | – | 18 | ns | Vdd = 4.5 to 5.25V, 10% - 90% |
| T _{FallF} | Fall Time, Normal Strong Mode, Cload = 50 pF | 2 | – | 18 | ns | Vdd = 4.5 to 5.25V, 10% - 90% |
| T _{RiseS} | Rise Time, Slow Strong Mode, Cload = 50 pF | 7 | 27 | – | ns | Vdd = 3 to 5.25V, 10% - 90% |
| T _{FallS} | Fall Time, Slow Strong Mode, Cload = 50 pF | 7 | 22 | – | ns | Vdd = 3 to 5.25V, 10% - 90% |

Table 3-17. 2.7V AC GPIO Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|--------------------|--|-----|-----|-----|-------|------------------------------|
| F _{GPIO} | GPIO Operating Frequency | 0 | – | 3 | MHz | Normal Strong Mode |
| T _{RiseF} | Rise Time, Normal Strong Mode, Cload = 50 pF | 6 | – | 50 | ns | Vdd = 2.4 to 3.0V, 10% - 90% |
| T _{FallF} | Fall Time, Normal Strong Mode, Cload = 50 pF | 6 | – | 50 | ns | Vdd = 2.4 to 3.0V, 10% - 90% |
| T _{RiseS} | Rise Time, Slow Strong Mode, Cload = 50 pF | 18 | 40 | 120 | ns | Vdd = 2.4 to 3.0V, 10% - 90% |
| T _{FallS} | Fall Time, Slow Strong Mode, Cload = 50 pF | 18 | 40 | 120 | ns | Vdd = 2.4 to 3.0V, 10% - 90% |

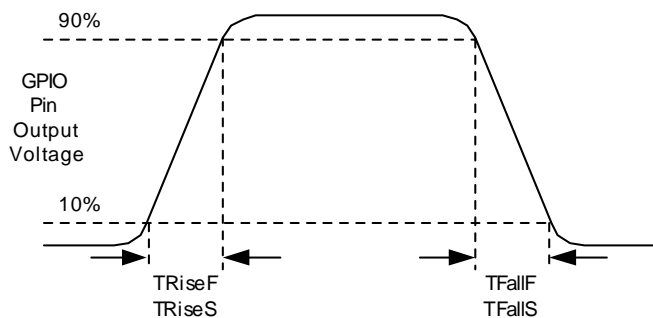


Figure 3-5. GPIO Timing Diagram

3.4.3 AC Operational Amplifier Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 2.4V to 3.0V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C and are for design guidance only.

Table 3-18. AC Operational Amplifier Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|-------------------|--|-----|-----|------------|----------|---|
| T _{COMP} | Comparator Mode Response Time, 50 mV Overdrive | | | 100 200 | ns ns | V _{DD} ≥ 3.0V. 2.4V < V _{CC} < 3.0V. |

3.4.4 AC Analog Mux Bus Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 2.4V to 3.0V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C and are for design guidance only.

Table 3-19. AC Analog Mux Bus Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|-----------------|-------------|-----|-----|------|-------|-------|
| F _{SW} | Switch Rate | – | – | 3.17 | MHz | |

3.4.5 AC Digital Block Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 2.4V to 3.0V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C and are for design guidance only.

Table 3-20. 5V and 3.3V AC Digital Block Specifications

| Function | Description | Min | Typ | Max | Units | Notes |
|-------------------|--|-----------------|-----|------|-------|---|
| All Functions | Maximum Block Clocking Frequency (> 4.75V) | | | 49.2 | MHz | 4.75V < V _{DD} < 5.25V. |
| | Maximum Block Clocking Frequency (< 4.75V) | | | 24.6 | MHz | 3.0V < V _{DD} < 4.75V. |
| Timer | Capture Pulse Width | 50 ^a | – | – | ns | |
| | Maximum Frequency, No Capture | – | – | 49.2 | MHz | 4.75V < V _{DD} < 5.25V. |
| | Maximum Frequency, With or Without Capture | – | – | 24.6 | MHz | |
| Counter | Enable Pulse Width | 50 | – | – | ns | |
| | Maximum Frequency, No Enable Input | – | – | 49.2 | MHz | 4.75V < V _{DD} < 5.25V. |
| | Maximum Frequency, Enable Input | – | – | 24.6 | MHz | |
| Dead Band | Kill Pulse Width: | | | | | |
| | Asynchronous Restart Mode | 20 | – | – | ns | |
| | Synchronous Restart Mode | 50 | – | – | ns | |
| | Disable Mode | 50 | – | – | ns | |
| | Maximum Frequency | – | – | 49.2 | MHz | 4.75V < V _{DD} < 5.25V. |
| CRCPRS (PRS Mode) | Maximum Input Clock Frequency | – | – | 49.2 | MHz | 4.75V < V _{DD} < 5.25V. |
| CRCPRS (CRC Mode) | Maximum Input Clock Frequency | – | – | 24.6 | MHz | |
| SPIM | Maximum Input Clock Frequency | – | – | 8.2 | MHz | Maximum data rate at 4.1 MHz due to 2 x over clocking. |
| SPIS | Maximum Input Clock Frequency | – | – | 4.1 | MHz | |
| | Width of SS_ Negated Between Transmissions | 50 | – | – | ns | |
| Transmitter | Maximum Input Clock Frequency | – | – | 24.6 | MHz | Maximum data rate at 3.08 MHz due to 8 x over clocking. |
| Receiver | Maximum Input Clock Frequency | – | – | 24.6 | MHz | Maximum data rate at 3.08 MHz due to 8 x over clocking. |

a. 50 ns minimum input pulse width is based on the input synchronizers running at 12 MHz (84 ns nominal period).

Table 3-21. 2.7V AC Digital Block Specifications

| Function | Description | Min | Typ | Max | Units | Notes |
|-------------------|--|------------------|-----|------|-------|---|
| All Functions | Maximum Block Clocking Frequency | | | 12.7 | MHz | 2.4V < Vdd < 3.0V. |
| Timer | Capture Pulse Width | 100 ^a | – | – | ns | |
| | Maximum Frequency, With or Without Capture | – | – | 12.7 | MHz | |
| Counter | Enable Pulse Width | 100 | – | – | ns | |
| | Maximum Frequency, No Enable Input | – | – | 12.7 | MHz | |
| | Maximum Frequency, Enable Input | – | – | 12.7 | MHz | |
| Dead Band | Kill Pulse Width: | | | | | |
| | Asynchronous Restart Mode | 20 | – | – | ns | |
| | Synchronous Restart Mode | 100 | – | – | ns | |
| | Disable Mode | 100 | – | – | ns | |
| | Maximum Frequency | – | – | 12.7 | MHz | |
| CRCPRS (PRS Mode) | Maximum Input Clock Frequency | – | – | 12.7 | MHz | |
| CRCPRS (CRC Mode) | Maximum Input Clock Frequency | – | – | 12.7 | MHz | |
| SPIIM | Maximum Input Clock Frequency | – | – | 6.35 | MHz | Maximum data rate at 3.17 MHz due to 2 x over clocking. |
| SPIS | Maximum Input Clock Frequency | – | – | 4.1 | MHz | |
| | Width of SS_ Negated Between Transmissions | 100 | – | – | ns | |
| Transmitter | Maximum Input Clock Frequency | – | – | 12.7 | MHz | Maximum data rate at 1.59 MHz due to 8 x over clocking. |
| Receiver | Maximum Input Clock Frequency | – | – | 12.7 | MHz | Maximum data rate at 1.59 MHz due to 8 x over clocking. |

a. 100 ns minimum input pulse width is based on the input synchronizers running at 12 MHz (84 ns nominal period).

3.4.6 AC External Clock Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C and are for design guidance only.

Table 3-22. 5V AC External Clock Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|---------|------------------------|-------|-----|------|---------------|-------|
| FOSCEXT | Frequency | 0.093 | – | 24.6 | MHz | |
| – | High Period | 20.6 | – | 5300 | ns | |
| – | Low Period | 20.6 | – | – | ns | |
| – | Power Up IMO to Switch | 150 | – | – | μs | |

Table 3-23. 3.3V AC External Clock Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|---------|---|-------|-----|------|---------------|---|
| FOSCEXT | Frequency with CPU Clock divide by 1 | 0.093 | – | 12.3 | MHz | Maximum CPU frequency is 12 MHz at 3.3V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements. |
| FOSCEXT | Frequency with CPU Clock divide by 2 or greater | 0.186 | – | 24.6 | MHz | If the frequency of the external clock is greater than 12 MHz, the CPU clock divider must be set to 2 or greater. In this case, the CPU clock divider will ensure that the fifty percent duty cycle requirement is met. |
| – | High Period with CPU Clock divide by 1 | 41.7 | – | 5300 | ns | |
| – | Low Period with CPU Clock divide by 1 | 41.7 | – | – | ns | |
| – | Power Up IMO to Switch | 150 | – | – | μs | |

Table 3-24. 2.7V AC External Clock Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|---------|---|-------|-----|------|---------------|--|
| FOSCEXT | Frequency with CPU Clock divide by 1 | 0.093 | – | 3.08 | MHz | Maximum CPU frequency is 3 MHz at 2.7V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements. |
| FOSCEXT | Frequency with CPU Clock divide by 2 or greater | 0.186 | – | 6.35 | MHz | If the frequency of the external clock is greater than 3 MHz, the CPU clock divider must be set to 2 or greater. In this case, the CPU clock divider will ensure that the fifty percent duty cycle requirement is met. |
| – | High Period with CPU Clock divide by 1 | 160 | – | 5300 | ns | |
| – | Low Period with CPU Clock divide by 1 | 160 | – | – | ns | |
| – | Power Up IMO to Switch | 150 | – | – | μs | |

3.4.7 AC Programming Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C and are for design guidance only.

Table 3-25. AC Programming Specifications

| Symbol | Description | Min | Typ | Max | Units | Notes |
|----------------------|--|-----|-----|-----|-------|-----------------------------|
| T _R SCLK | Rise Time of SCLK | 1 | – | 20 | ns | |
| T _F SCLK | Fall Time of SCLK | 1 | – | 20 | ns | |
| T _S SCLK | Data Set up Time to Falling Edge of SCLK | 40 | – | – | ns | |
| T _H SCLK | Data Hold Time from Falling Edge of SCLK | 40 | – | – | ns | |
| F _S CLK | Frequency of SCLK | 0 | – | 8 | MHz | |
| T _{ERASEB} | Flash Erase Time (Block) | – | 15 | – | ms | |
| T _{WRITE} | Flash Block Write Time | – | 30 | – | ms | |
| T _D SCLK | Data Out Delay from Falling Edge of SCLK | – | – | 45 | ns | 3.6 < V _{DD} |
| T _D SCLK3 | Data Out Delay from Falling Edge of SCLK | – | – | 50 | ns | 3.0 ≤ V _{DD} ≤ 3.6 |
| T _D SCLK2 | Data Out Delay from Falling Edge of SCLK | – | – | 70 | ns | 2.4 ≤ V _{DD} ≤ 3.0 |

3.4.8 AC I²C Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, 3.0V to 3.6V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, or 2.4V to 3.0V and $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V, 3.3V, or 2.7V at 25°C and are for design guidance only.

Table 3-26. AC Characteristics of the I²C SDA and SCL Pins for V_{DD} ≥ 3.0V

| Symbol | Description | Standard Mode | | Fast Mode | | Units | Notes |
|------------------------------------|--|---------------|-----|------------------|-----|-------|-------|
| | | Min | Max | Min | Max | | |
| F _S CL _{I2C} | SCL Clock Frequency | 0 | 100 | 0 | 400 | kHz | |
| T _H DSTAI _{2C} | Hold Time (repeated) START Condition. After this period, the first clock pulse is generated. | 4.0 | – | 0.6 | – | μs | |
| T _{LOW} I _{2C} | LOW Period of the SCL Clock | 4.7 | – | 1.3 | – | μs | |
| T _{HIGH} I _{2C} | HIGH Period of the SCL Clock | 4.0 | – | 0.6 | – | μs | |
| T _S USTA _{2C} | Set-up Time for a Repeated START Condition | 4.7 | – | 0.6 | – | μs | |
| T _H DDAT _{I2C} | Data Hold Time | 0 | – | 0 | – | μs | |
| T _S UDAT _{I2C} | Data Set-up Time | 250 | – | 100 ^a | – | ns | |
| T _S USTOI _{2C} | Set-up Time for STOP Condition | 4.0 | – | 0.6 | – | μs | |
| T _B UF _{I2C} | Bus Free Time Between a STOP and START Condition | 4.7 | – | 1.3 | – | μs | |
| T _S PI _{2C} | Pulse Width of spikes are suppressed by the input filter. | – | – | 0 | 50 | ns | |

- a. A Fast-Mode I²C-bus device can be used in a Standard-Mode I²C-bus system, but the requirement t_{SU, DAT} ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line t_{rmax} + t_{SU, DAT} = 1000 + 250 = 1250 ns (according to the Standard-Mode I²C-bus specification) before the SCL line is released.

Table 3-27. 2.7V AC Characteristics of the I²C SDA and SCL Pins (Fast Mode not Supported)

| Symbol | Description | Standard Mode | | Fast Mode | | Units | Notes |
|------------------------------------|--|---------------|-----|-----------|-----|-------|-------|
| | | Min | Max | Min | Max | | |
| F _S CL _{I2C} | SCL Clock Frequency | 0 | 100 | – | – | kHz | |
| T _H DSTAI _{2C} | Hold Time (repeated) START Condition. After this period, the first clock pulse is generated. | 4.0 | – | – | – | μs | |
| T _{LOW} I _{2C} | LOW Period of the SCL Clock | 4.7 | – | – | – | μs | |
| T _{HIGH} I _{2C} | HIGH Period of the SCL Clock | 4.0 | – | – | – | μs | |
| T _S USTA _{2C} | Set-up Time for a Repeated START Condition | 4.7 | – | – | – | μs | |
| T _H DDAT _{I2C} | Data Hold Time | 0 | – | – | – | μs | |

4. Packaging Information



This chapter illustrates the packaging specifications for the CY8C21x34 PSoC device, along with the thermal impedances for each package.

Important Note Emulation tools may require a larger area on the target PCB than the chip's footprint. For a detailed description of the emulation tools' dimensions, refer to the document titled *PSoC Emulator Pod Dimensions* at <http://www.cypress.com/support/link.cfm?mr=poddim>.

4.1 Packaging Dimensions

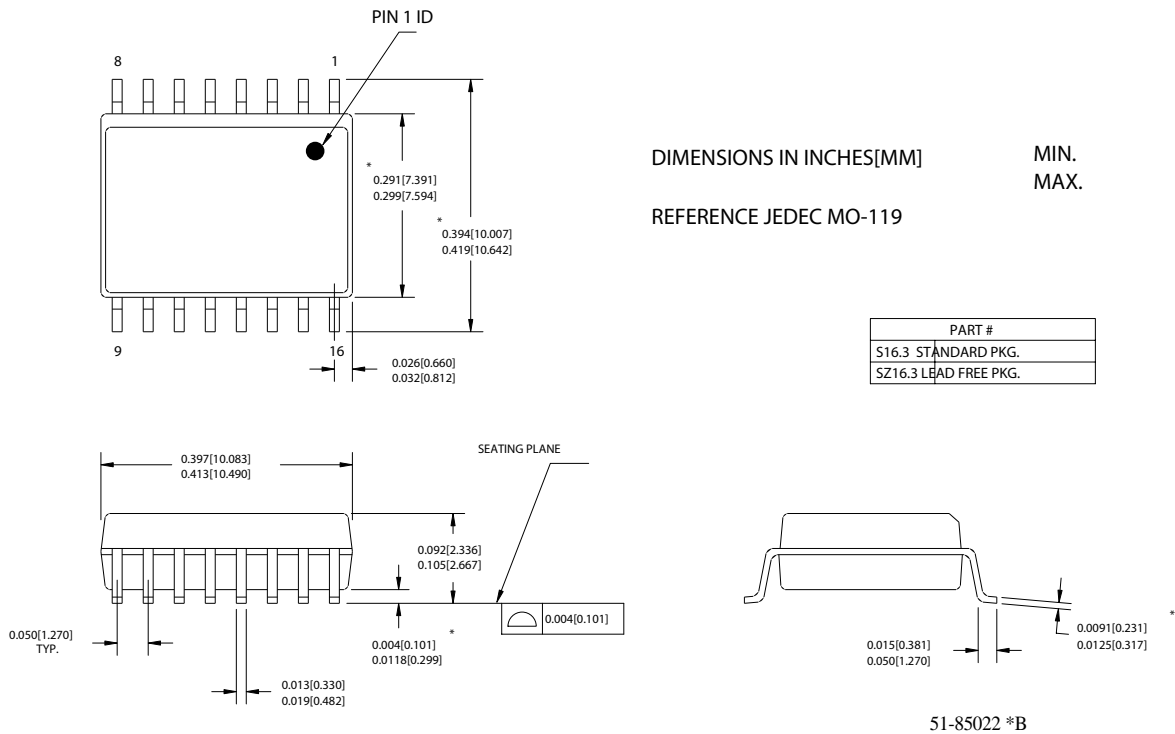


Figure 4-1. 16-Lead (150-Mil) SOIC

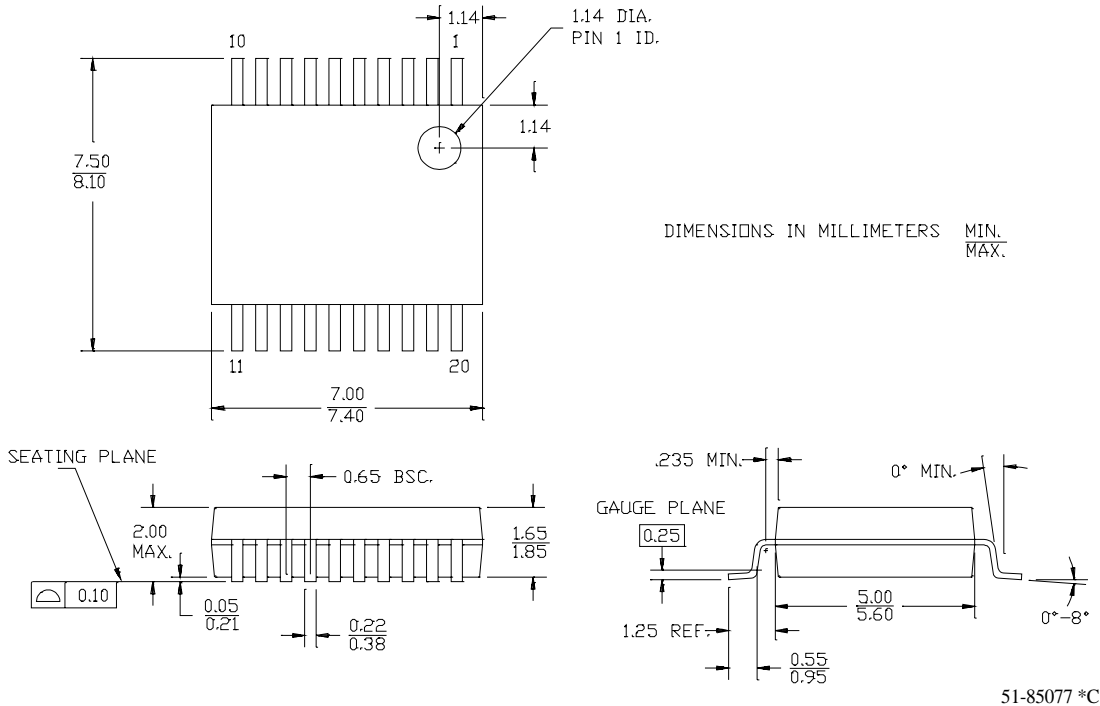


Figure 4-2. 20-Lead (210-MIL) SSOP

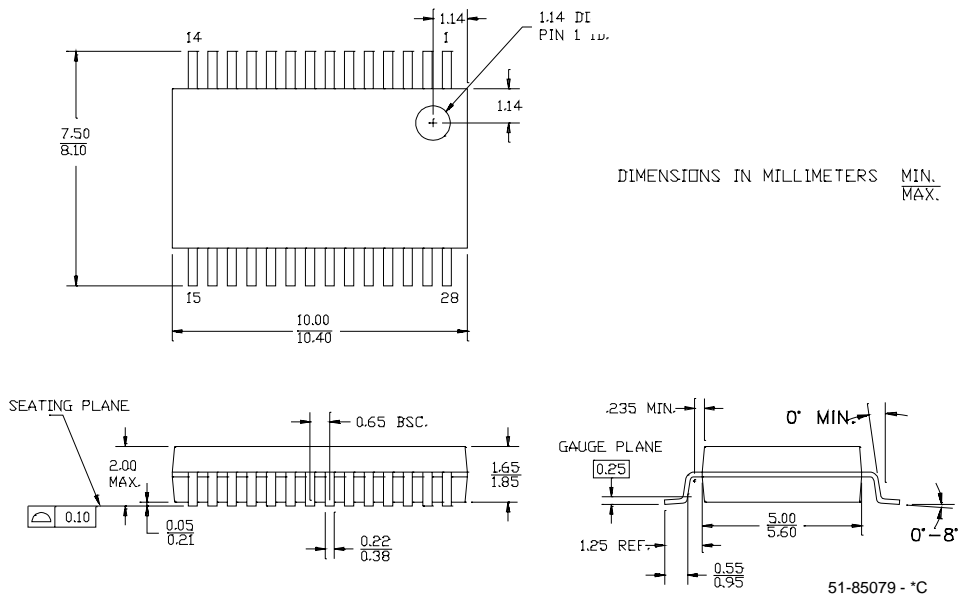
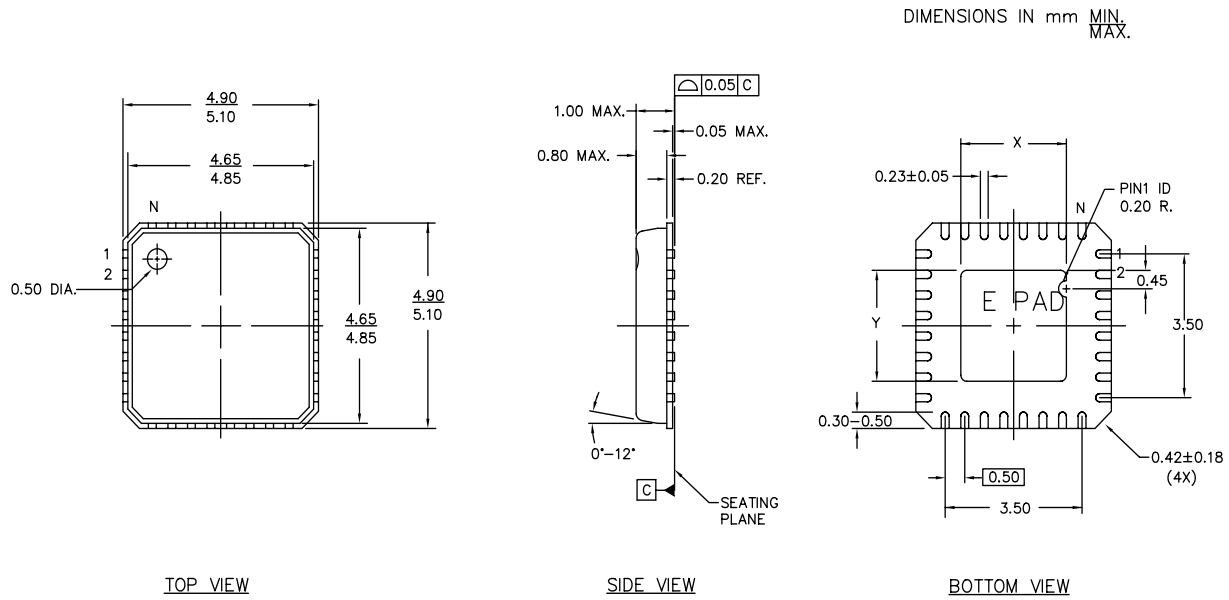


Figure 4-3. 28-Lead (210-Mil) SSOP



NOTE: E-PAD X, Y DIMENSION VARIES BY PRODUCT DUE TO DIE SIZE VARIABLE.

JEDEC # MO-220

51-85188 **

Figure 4-4. 32-Lead (5x5 mm) MLF

4.2 Thermal Impedances

Table 4-1. Thermal Impedances per Package

| Package | Typical θ_{JA} * |
|---------|-------------------------|
| 16 SOIC | 96 °C/W |
| 20 SSOP | 95 °C/W |
| 28 SSOP | 101 °C/W |
| 32 MLF | 22 °C/W |

* $T_J = T_A + \text{Power} \times \theta_{JA}$

4.3 Solder Reflow Peak Temperature

Following is the minimum solder reflow peak temperature to achieve good solderability.

Table 4-2. Solder Reflow Peak Temperature

| Package | Minimum Peak Temperature* | Maximum Peak Temperature |
|---------|---------------------------|--------------------------|
| 16 SOIC | 220°C | 260°C |
| 20 SSOP | 240°C | 260°C |
| 28 SSOP | 240°C | 260°C |
| 32 MLF | 220°C | 260°C |

*Higher temperatures may be required based on the solder melting point. Typical temperatures for solder are 220+/-5°C with Sn-Pb or 245+/-5°C with Sn-Ag-Cu paste. Refer to the solder manufacturer specifications.

5. Ordering Information



The following table lists the CY8C21x34 PSoC device's key package features and ordering codes.

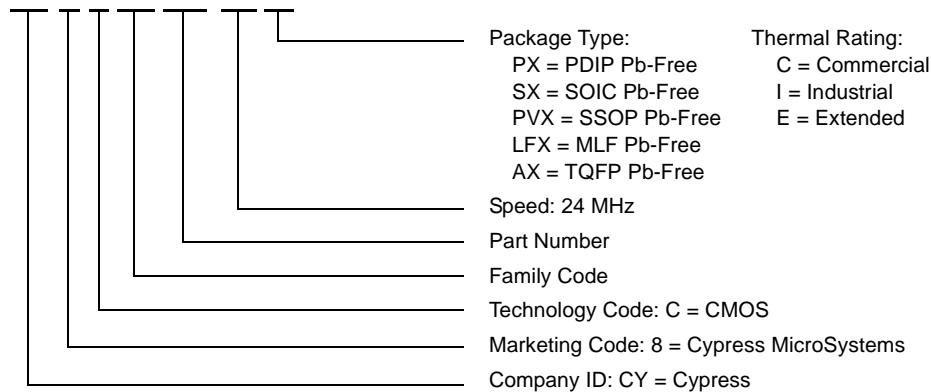
CY8C21x34 PSoC Device Key Features and Ordering Information

| Package | Ordering Code | Flash (Bytes) | SRAM (Bytes) | Switch Mode Pump | Temperature Range | Digital Blocks | Analog Blocks | Digital IO Pins | Analog Inputs ^a | Analog Outputs | XRES Pin |
|---|-------------------|---------------|--------------|------------------|-------------------|----------------|---------------|-----------------|----------------------------|----------------|----------|
| 16 Pin (150-Mil) SOIC | CY8C21234-24SXI | 8K | 512 | Yes | -40°C to +85°C | 4 | 4 | 12 | 12 ^a | 0 | No |
| 16 Pin (150-Mil) SOIC (Tape and Reel) | CY8C21234-24SXIT | 8K | 512 | Yes | -40°C to +85°C | 4 | 4 | 12 | 12 ^a | 0 | No |
| 20 Pin (300-Mil) SSOP | CY8C21334-24PVXI | 8K | 512 | No | -40°C to +85°C | 4 | 4 | 16 | 16 ^a | 0 | Yes |
| 20 Pin (300-Mil) SSOP (Tape and Reel) | CY8C21334-24PVXIT | 8K | 512 | No | -40°C to +85°C | 4 | 4 | 16 | 16 ^a | 0 | Yes |
| 28 Pin (210-Mil) SSOP | CY8C21534-24PVXI | 8K | 512 | No | -40°C to +85°C | 4 | 4 | 24 | 24 ^a | 0 | Yes |
| 28 Pin (210-Mil) SSOP (Tape and Reel) | CY8C21534-24PVXIT | 8K | 512 | No | -40°C to +85°C | 4 | 4 | 24 | 24 ^a | 0 | Yes |
| 32 Pin (5x5) MLF ^b | CY8C21434-24LFXI | 8K | 512 | No | -40°C to +85°C | 4 | 4 | 28 | 28 ^a | 0 | Yes |
| 32 Pin (5x5) MLF ^b (Tape and Reel) | CY8C21434-24LFXIT | 8K | 512 | No | -40°C to +85°C | 4 | 4 | 28 | 28 ^a | 0 | Yes |
| 32 Pin (5x5) MLF ^b | CY8C21634-24LFXI | 8K | 512 | Yes | -40°C to +85°C | 4 | 4 | 26 | 26 ^a | 0 | Yes |
| 32 Pin (5x5) MLF ^b (Tape and Reel) | CY8C21634-24LFXIT | 8K | 512 | Yes | -40°C to +85°C | 4 | 4 | 26 | 26 ^a | 0 | Yes |

- a. All Digital IO Pins also connect to the common analog mux.
 b. Refer to the "32-Pin Part Pinout" on page 11 for pin differences.

5.1 Ordering Code Definitions

CY 8 C 21 xxx-24xx



6. Sales and Service Information



To obtain information about Cypress Microsystems or PSoC sales and technical support, reference the following information or go to the section titled "Getting Started" on page 4 in this document.

Cypress Microsystems

2700 162nd Street SW
Building D
Lynnwood, WA 98037

Phone: 800.669.0557
Facsimile: 425.787.4641

Web Sites: Company Information – <http://www.cypress.com>
Sales – http://www.cypress.com/aboutus/sales_locations.cfm
Technical Support – <http://www.cypress.com/support/login.cfm>

6.1 Revision History

| Document Title: CY8C21234, CY8C21334, CY8C21434, CY8C21534, and CY8C21634 PSoC Mixed-Signal Array Final Data Sheet | | | | |
|---|--------|----------------------|------------------|---|
| Document Number: 38-12025 | | | | |
| Revision | ECN # | Issue Date | Origin of Change | Description of Change |
| ** | 227340 | 05/19/2004 | HMT | New silicon and document (Revision **). |
| *A | 235992 | See ECN | SFV | Updated Overview and Electrical Spec. chapters, along with revisions to the 24-pin pinout part. Revised the register mapping tables. Added a SSOP 28-pin part. |
| *B | 248572 | See ECN | SFV | Changed title to include all part #s. Changed 28-pin SSOP from CY8C21434 to CY8C21534. Changed pin 9 on the 28-pin SSOP from SMP pin to Vss pin. Added SMP block to architecture diagram. Update Electrical Specifications. Added another 32-pin MLF part: CY8C21634. |
| *C | 277832 | See ECN | HMT | Verify data sheet standards from SFV memo. Add Analog Input Mux to applicable pin outs. Update PSoC Characteristics table. Update diagrams and specs. Final. |
| *D | 285293 | See ECN | HMT | Update 2.7V DC GPIO spec. Add Reflow Peak Temp. table. |
| *E | 301739 | See ECN | HMT | DC Chip-Level Specification changes. Update links to new CY.com Portal. |
| Distribution: External/Public | | Posting: None | | |

6.2 Copyrights and Code Protection

© Cypress Microsystems, Inc. 2004. All rights reserved. PSoC™, PSoC Designer™, and Programmable System-on-Chip™ are trademarks of Cypress Microsystems, Inc. All other trademarks or registered trademarks referenced herein are property of the respective corporations.

The information contained herein is subject to change without notice. Cypress Microsystems assumes no responsibility for the use of any circuitry other than circuitry embodied in a Cypress Microsystems product. Nor does it convey or imply any license under patent or other rights. Cypress Microsystems does not authorize its products for use as critical components in life-support systems where a malfunction or failure may reasonably be expected to result in significant injury to the user. The inclusion of Cypress Microsystems products in life-support systems application implies that the manufacturer assumes all risk of such use and in doing so indemnifies Cypress Microsystems against all charges. Cypress Microsystems products are not warranted nor intended to be used for medical, life-support, life-saving, critical control or safety applications, unless pursuant to an express written agreement with Cypress Microsystems.

Note the following details of the Flash code protection features on Cypress Microsystems devices.

Cypress Microsystems products meet the specifications contained in their particular Cypress Microsystems Data Sheets. Cypress Microsystems believes that its family of products is one of the most secure families of its kind on the market today, regardless of how they are used. There may be methods, unknown to Cypress Microsystems, that can breach the code protection features. Any of these methods, to our knowledge, would be dishonest and possibly illegal. Neither Cypress Microsystems nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Cypress Microsystems is willing to work with the customer who is concerned about the integrity of their code. Code protection is constantly evolving. We at Cypress Microsystems are committed to continuously improving the code protection features of our products.